

Quad Remote Diode and Local Temperature Sensor with SMBus Interface

Check for Samples: [LM95214](#)

FEATURES

- Accurately Senses Die Temperature of 4 Remote ICs or Diode Junctions and Local Temperature
- Programmable Digital Filters and Analog Front End Filter
- 0.125°C LSb Temperature Resolution
- 0.03125°C LSb Remote Temperature Resolution with Digital Filter Enabled
- +127.875°C/–128°C and 0°C/255°C Remote Ranges
- Remote Diode Fault Detection, Model Selection and Offset Correction
- Mask and Status Register Support
- 3 Programmable TCRIT Outputs with Programmable Shared Hysteresis and Fault-Queue
- Programmable Conversion Rate and Shutdown Mode One-shot Conversion Control
- SMBus 2.0 Compatible Interface, Supports TIMEOUT
- Three-level Address Pin
- 14-pin WSON Package

KEY SPECIFICATIONS

- Local Temperature Accuracy $\pm 2.0^{\circ}\text{C}$ (max)
- Remote Diode Temperature Accuracy $\pm 1.1^{\circ}\text{C}$ (Max)
- Supply Voltage 3.0V to 3.6V
- Average Supply Current (1Hz Conversion Rate) 0.57 mA (Typ)

APPLICATIONS

- Processor/Computer System Thermal Management
 - (e.g. Laptop, Desktop, Workstations, Server)
- Electronic Test Equipment
- Office Electronics

DESCRIPTION

The LM95214 is an 11-bit digital temperature sensor with a 2-wire System Management Bus (SMBus) interface that can very accurately monitor the temperature of four remote diodes as well as its own temperature. The four remote diodes can be external devices such as microprocessors, graphics processors that target the ideality of a 2N3904 transistor or diode-connected 2N3904s.

The LM95214 reports temperature in two different formats for +127.875°C/–128°C range and 0°C/255°C range. The LM95214 TCRIT1, TCRIT2 and TCRIT3 outputs are triggered when any unmasked channel exceeds its corresponding programmable limit and can be used to shutdown the system, to turn on the system fans or as a microcontroller interrupt function. The current status of the TCRIT1, TCRIT2 and TCRIT3 pins can be read back from the status registers. Mask registers are available for further control of the TCRIT outputs.

Two LM95214 remote temperature channels have programmable digital filters while the other two remote channels utilize a fault-queue to minimize unwanted TCRIT events when temperature spikes are encountered.

For optimum flexibility and accuracy, each LM95214 channel includes registers for offset correction. A three-level address pin allows connection of up to 3 LM95214s to the same SMBus master. The LM95214 includes power saving functions such as: programmable conversion rate, shutdown mode, and disabling of unused channels.

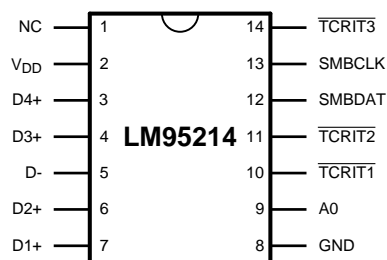


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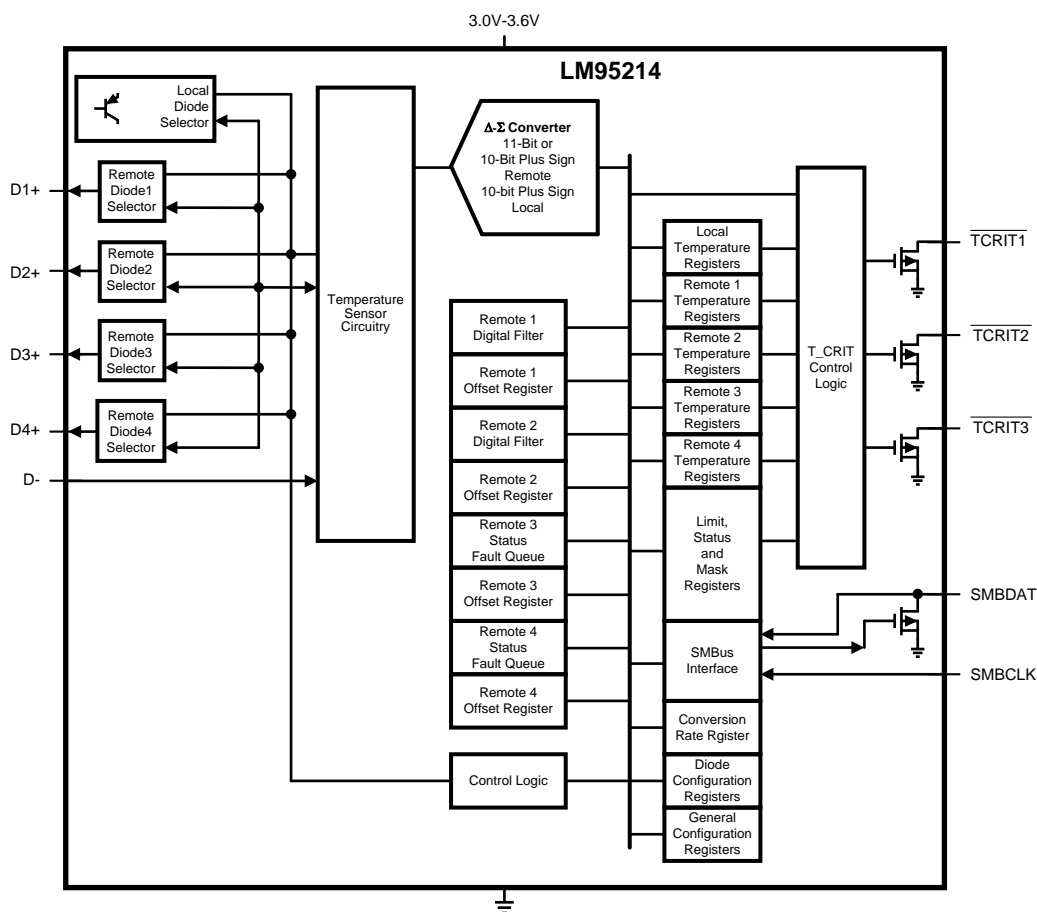
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Connection Diagram



**Figure 1. WSON-14
TOP VIEW**

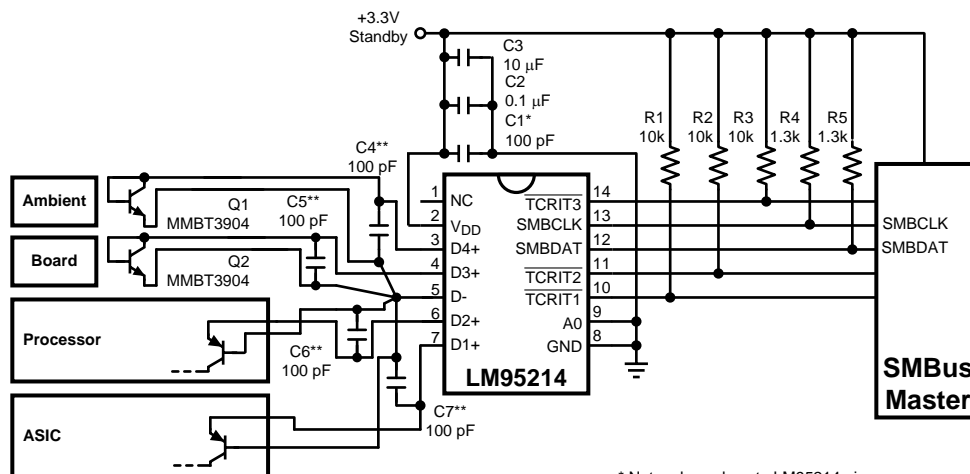
Simplified Block Diagram



Pin Descriptions

| Label | Pin # | Function | Typical Connection |
|----------------------------|-------|--|---|
| NC | 1 | No Connect | Not connected. May be left floating, connected to GND or V_{DD} . |
| V_{DD} | 2 | Positive Supply Voltage Input | DC Voltage from 3.0V to 3.6V. V_{DD} should be bypassed with a 0.1 μ F capacitor in parallel with 100 pF. The 100 pF capacitor should be placed as close as possible to the power supply pin. Noise should be kept below 200 mVp-p, a 10 μ F capacitor may be required to achieve this. |
| D4+ | 3 | Diode Current Source | Fourth Diode Anode. Connected to remote discrete diode-connected transistor junction or to the diode-connected transistor junction on a remote IC whose die temperature is being sensed. A capacitor is not required between D4+ and D-. A 100 pF capacitor between D4+ and D- can be added and may improve performance in noisy systems. Float this pin if this thermal diode is not used. |
| D3+ | 4 | Diode Current Source | Third Diode Anode. Connected to remote discrete diode-connected transistor junction or to the diode-connected transistor junction on a remote IC whose die temperature is being sensed. A capacitor is not required between D3+ and D-. A 100 pF capacitor between D3+ and D- can be added and may improve performance in noisy systems. Float this pin if this thermal diode is not used. |
| D- | 5 | Diode Return Current Sink | All Diode Cathodes. Common D- pin for all four remote diodes. |
| D2+ | 6 | Diode Current Source | Second Diode Anode. Connected to remote discrete diode-connected transistor junction or to the diode-connected transistor junction on a remote IC whose die temperature is being sensed. A capacitor is not required between D2+ and D-. A 100 pF capacitor between D2+ and D- can be added and may improve performance in noisy systems. Float this pin if this thermal diode is not used. |
| D1+ | 7 | Diode Current Source | First Diode Anode. Connected to remote discrete diode-connected transistor junction or to the diode-connected transistor junction on a remote IC whose die temperature is being sensed. A capacitor is not required between D1+ and D-. A 100 pF capacitor between D1+ and D- can be added and may improve performance in noisy systems. Float this pin if this thermal diode is not used. |
| GND | 8 | Power Supply Ground | System low noise ground. |
| A0 | 9 | Digital Input | SMBus slave address select pin. Selects one of three addresses. Can be tied to V_{DD} , GND, or to the middle of a resistor divider connected between V_{DD} and GND. |
| $\overline{\text{TCRIT1}}$ | 10 | Digital Output, Open-Drain | Critical temperature output 1. Requires pull-up resistor. Active "LOW". |
| $\overline{\text{TCRIT2}}$ | 11 | Digital Output, Open-Drain | Critical temperature output 2. Requires pull-up resistor. Active "LOW". |
| SMBDAT | 12 | SMBus Bidirectional Data Line, Open-Drain Output | From and to Controller; may require an external pull-up resistor |
| SMBCLK | 13 | SMBus Clock Input | From Controller; may require an external pull-up resistor |
| $\overline{\text{TCRIT3}}$ | 14 | Digital Output, Open-Drain | Critical temperature output 3. Requires pull-up resistor. Active "LOW". |

Typical Application



* Note, place close to LM95214 pins.

** Note, optional - place close to LM95214 pins.



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

Absolute Maximum Ratings⁽¹⁾

| | | |
|--|---------------------|------------------------------------|
| Supply Voltage | | –0.3 to 6.0V |
| Voltage at SMBDAT, SMBCLK, $\overline{\text{TCRIT1}}$, $\overline{\text{TCRIT2}}$, $\overline{\text{TCRIT3}}$ | | –0.5 to 6.0 |
| Voltage at Other Pins | | –0.3 to ($V_{\text{DD}} + 0.3$)V |
| D– Input Current | | ±1 mA |
| Input Current at All Other Pins ⁽²⁾ | | ±5 mA |
| Package Input Current ⁽²⁾ | | 30 mA |
| Output Sink Current SMBDAT, $\overline{\text{TCRIT1}}$, $\overline{\text{TCRIT2}}$, $\overline{\text{TCRIT3}}$ | | 10 mA |
| Storage Temperature | | –65 to +150°C |
| ESD Susceptibility ⁽³⁾ | Human Body Model | 2000V |
| | Machine Model | 200V |
| | Charge Device Model | 1000V |
| Soldering process must comply with Texas Instruments' reflow temperature profile specifications. Refer to http://www.ti.com/packaging ⁽⁴⁾ | | |

- (1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. DC and AC electrical specifications do not apply when operating the device beyond its rated operating conditions.
- (2) When the input voltage (V_I) at any pin exceeds the power supplies ($V_I < \text{GND}$ or $V_I > V_{DD}$), the current at that pin should be limited to 5 mA. Parasitic components and or ESD protection circuitry are shown in the table below for the LM95214's pins.
- (3) Human body model, 100 pF discharged through a 1.5 kΩ resistor. Machine model, 200 pF discharged directly into each pin. Charged Device Model (CDM) simulates a pin slowly acquiring charge (such as from a device sliding down the feeder in an automated assembler) then rapidly being discharged.
- (4) Reflow temperature profiles are different for packages containing lead (Pb) than for those that do not.

Operating Ratings⁽¹⁾⁽²⁾

| | |
|--|------------------------------------|
| Operating Temperature Range | –40 to +140°C |
| Electrical Characteristics Temperature Range | $T_{MIN} \leq T_A \leq T_{MAX}$ °C |
| LM95214CISD | –40 $\leq T_A \leq$ +125°C |
| Supply Voltage Range (V_{DD}) | +3.0 to +3.6V |

- (1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. DC and AC electrical specifications do not apply when operating the device beyond its rated operating conditions.
- (2) Thermal resistance junction-to-ambient when attached to a 4 layer printed circuit board per JEDEC standard JESD51-7:
 - 14-lead WSON = 90°C/W (no thermal vias, no airflow)
 - 14-lead WSON = 63°C/W (1 thermal via, no airflow)
 - 14-lead WSON = 43°C/W (6 thermal vias, no airflow)
 - 14-lead WSON = 31°C/W (6 thermal vias, 900 In. ft. / min. airflow)
Note, all quoted values include +15% error factor from nominal value.

Temperature-to-Digital Converter Electrical Characteristics

Unless otherwise noted, these specifications apply for $V_{DD} = +3.0\text{Vdc}$ to 3.6Vdc. **Boldface limits apply for $T_A = T_J = T_{MIN} \leq T_A \leq T_{MAX}$** ; all other limits $T_A = T_J = +25^\circ\text{C}$, unless otherwise noted.

| Parameter | Conditions | Typical ⁽¹⁾ | Limits ⁽²⁾ | Units (Limit) |
|--|---|------------------------|-----------------------|---------------|
| Temperature Error Using Local Diode | $T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$ ⁽³⁾ | ±1 | ±2 | °C (max) |
| Temperature Error Using an MMBT3904 Transistor Remote Diode ⁽⁴⁾ | $T_A = +25^\circ\text{C}$ to $+85^\circ\text{C}$ $T_D = +60^\circ\text{C}$ to $+100^\circ\text{C}$ | | ±1.1 | °C (max) |
| | $T_A = +25^\circ\text{C}$ to $+85^\circ\text{C}$ $T_D = -40^\circ\text{C}$ to $+125^\circ\text{C}$ | | ±1.3 | °C (max) |
| | $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$ $T_D = -40^\circ\text{C}$ to $+125^\circ\text{C}$ | | ±3.0 | °C (max) |
| | $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$ $T_D = 125^\circ\text{C}$ to $+140^\circ\text{C}$ | | ±3.3 | °C (max) |

- (1) Typicals are at $T_A = 25^\circ\text{C}$ and represent most likely parametric norm.
- (2) Limits are specified to AOQL (Average Outgoing Quality Level).
- (3) Local temperature accuracy does not include the effects of self-heating. The rise in temperature due to self-heating is the product of the internal power dissipation of the LM95214 and the thermal resistance. See [Note 2](#) under Operating Ratings table for the thermal resistance to be used in the self-heating calculation.
- (4) The accuracy of the LM95214CISD is ensured when using a typical MMBT3904 diode-connected transistor. For further information on other thermal diodes see applications [DIODE NON-IDEALITY](#).

Temperature-to-Digital Converter Electrical Characteristics (continued)

Unless otherwise noted, these specifications apply for $V_{DD} = +3.0V_{dc}$ to $3.6V_{dc}$. **Boldface limits apply for $T_A = T_J = T_{MIN} \leq T_A \leq T_{MAX}$** ; all other limits $T_A = T_J = +25^\circ C$, unless otherwise noted.

| Parameter | Conditions | Typical ⁽¹⁾ | Limits ⁽²⁾ | Units (Limit) |
|---|--|------------------------|--------------------------|--------------------|
| Local Diode Measurement Resolution | | 11 | | Bits |
| | | 0.125 | | $^\circ C$ |
| Remote Diode Measurement Resolution | Digital Filter Off | 11 | | Bits |
| | | 0.125 | | $^\circ C$ |
| | Digital Filter On (Remote Diodes 1 and 2 only) | 13 | | Bits |
| | | 0.03125 | | $^\circ C$ |
| Conversion Time of All Temperatures at the Fastest Setting ⁽⁵⁾ | All Channels are Enabled in Default State | 1100 | 1210 | ms (max) |
| | 1 External Channel | 31 | 34 | ms (max) |
| | Local only | 30 | 33 | ms (max) |
| Quiescent Current ⁽⁶⁾ | SMBus Inactive, 1Hz Conversion Rate, channels in default state | 570 | 800 | μA (max) |
| | Shutdown | 360 | | μA |
| D- Source Voltage | | 0.4 | | V |
| Remote Diode Source Current | High level | 160 | 230 | μA (max) |
| | Low level | 10 | | |
| Power-On Reset Threshold | Measured on V_{DD} input, falling edge | | 2.8 1.6 | V (max) V (min) |
| $\overline{TCRIT1}$ Pin Temperature Threshold | Default Diodes 1 and 2 only | +110 | | $^\circ C$ |
| $\overline{TCRIT2}$ Pin Temperature Threshold | Default all channels | +85 | | $^\circ C$ |
| $\overline{TCRIT3}$ Pin Temperature Threshold | Default Diodes 3 and 4 only | +85 | | $^\circ C$ |

(5) This specification is provided only to indicate how often temperature data is updated. The LM95214 can be read at any time without regard to conversion state (and will yield last conversion result).

(6) Quiescent current will not increase substantially with an SMBus communication.

Logic Electrical Characteristics

DIGITAL DC CHARACTERISTICS

Unless otherwise noted, these specifications apply for $V_{DD} = +3.0V_{dc}$ to $3.6V_{dc}$. **Boldface limits apply for $T_A = T_J = T_{MIN}$ to T_{MAX}** ; all other limits $T_A = T_J = +25^\circ C$, unless otherwise noted.

| Symbol | Parameter | Conditions | Typical ⁽¹⁾ | Limits ⁽²⁾ | Units (Limit) |
|------------------------------|--|-------------------|------------------------|--|---------------|
| SMBDAT, SMBCLK INPUTS | | | | | |
| $V_{IN(1)}$ | Logical "1" Input Voltage | | | 2.1 | V (min) |
| $V_{IN(0)}$ | Logical "0" Input Voltage | | | 0.8 | V (max) |
| $V_{IN(HYST)}$ | SMBDAT and SMBCLK Digital Input Hysteresis | | 400 | | mV |
| $I_{IN(1)}$ | Logical "1" Input Current | $V_{IN} = V_{DD}$ | 0.005 | 10 | μA (max) |
| $I_{IN(0)}$ | Logical "0" Input Current | $V_{IN} = 0V$ | -0.005 | -10 | μA (max) |
| C_{IN} | Input Capacitance | | 5 | | pF |
| A0 DIGITAL INPUT | | | | | |
| V_{IH} | Input High Voltage | | | $0.90 \times V_{DD}$ | V (min) |
| V_{IM} | Input Middle Voltage | | | $0.57 \times V_{DD}$ | V (max) |
| | | | | $0.43 \times V_{DD}$ | V (min) |
| V_{IL} | Input Low Voltage | | | $0.10 \times V_{DD}$ | V (max) |
| $I_{IN(1)}$ | Logical "1" Input Current | $V_{IN} = V_{DD}$ | -0.005 | -10 | μA (min) |
| $I_{IN(0)}$ | Logical "0" Input Current | $V_{IN} = 0V$ | 0.005 | 10 | μA (max) |
| C_{IN} | Input Capacitance | | 5 | | pF |

(1) Typicals are at $T_A = 25^\circ C$ and represent most likely parametric norm.

(2) Limits are specified to AOQL (Average Outgoing Quality Level).

Logic Electrical Characteristics (continued)

DIGITAL DC CHARACTERISTICS

Unless otherwise noted, these specifications apply for $V_{DD} = +3.0\text{Vdc}$ to 3.6Vdc . **Boldface limits apply for $T_A = T_J = T_{MIN}$ to T_{MAX}** ; all other limits $T_A = T_J = +25^\circ\text{C}$, unless otherwise noted.

| Symbol | Parameter | Conditions | Typical ⁽¹⁾ | Limits ⁽²⁾ | Units (Limit) |
|--|---|--|------------------------|--------------------------|---------------------|
| SMBDAT, $\overline{\text{TCRIT1}}$, $\overline{\text{TCRIT2}}$, $\overline{\text{TCRIT3}}$ DIGITAL OUTPUTS | | | | | |
| I_{OH} | High Level Output Current | $V_{OH} = V_{DD}$ | | 10 | μA (max) |
| $V_{OL(\text{SMBDAT})}$ | SMBus Low Level Output Voltage | $I_{OL} = 4\text{ mA}$ $I_{OL} = 6\text{ mA}$ | | 0.4 0.6 | V (max) V (max) |
| $V_{OL(\overline{\text{TCRIT}})}$ | $\overline{\text{TCRIT1}}$, $\overline{\text{TCRIT2}}$, $\overline{\text{TCRIT3}}$ Low Level Output Voltage | $I_{OL} = 6\text{ mA}$ | | 0.4 | V (max) |
| C_{OUT} | Digital Output Capacitance | | 5 | | pF |

SMBus DIGITAL SWITCHING CHARACTERISTICS

Unless otherwise noted, these specifications apply for $V_{DD} = +3.0\text{ Vdc}$ to $+3.6\text{ Vdc}$, C_L (load capacitance) on output lines = 80 pF. **Boldface limits apply for $T_A = T_J = T_{MIN}$ to T_{MAX}** ; all other limits $T_A = T_J = +25^\circ\text{C}$, unless otherwise noted.

The switching characteristics of the LM95214 fully meet or exceed the published specifications of the SMBus version 2.0. The following parameters are the timing relationships between SMBCLK and SMBDAT signals related to the LM95214. They adhere to but are not necessarily the SMBus bus specifications.

| Symbol | Parameter | Conditions | Typical ⁽¹⁾ | Limits ⁽²⁾ | Units (Limit) |
|----------------------|---|---|------------------------|---------------------------|---------------------------------|
| f_{SMB} | SMBus Clock Frequency | | | 100 10 | kHz (max) kHz (min) |
| t_{LOW} | SMBus Clock Low Time | from $V_{IN(0)\text{max}}$ to $V_{IN(0)\text{max}}$ | | 4.7 25 | μs (min) ms (max) |
| t_{HIGH} | SMBus Clock High Time | from $V_{IN(1)\text{min}}$ to $V_{IN(1)\text{min}}$ | | 4.0 | μs (min) |
| $t_{\text{R,SMB}}$ | SMBus Rise Time | See ⁽³⁾ | 1 | | μs (max) |
| $t_{\text{F,SMB}}$ | SMBus Fall Time | See ⁽⁴⁾ | 0.3 | | μs (max) |
| t_{OF} | Output Fall Time | $C_L = 400\text{ pF}$, $I_O = 3\text{ mA}$ ⁽⁴⁾ | | 250 | ns (max) |
| t_{TIMEOUT} | SMBDAT and SMBCLK Time Low for Reset of Serial Interface ⁽⁵⁾ | | | 25 35 | ms (min) ms (max) |
| $t_{\text{SU;DAT}}$ | Data In Setup Time to SMBCLK High | | | 250 | ns (min) |
| $t_{\text{HD;DAT}}$ | Data Out Stable after SMBCLK Low | | | 300 1075 | ns (min) ns (max) |
| $t_{\text{HD;STA}}$ | Start Condition SMBDAT Low to SMBCLK Low (Start condition hold before the first clock falling edge) | | | 100 | ns (min) |
| $t_{\text{SU;STO}}$ | Stop Condition SMBCLK High to SMBDAT Low (Stop Condition Setup) | | | 100 | ns (min) |
| $t_{\text{SU;STA}}$ | SMBus Repeated Start-Condition Setup Time, SMBCLK High to SMBDAT Low | | | 0.6 | μs (min) |
| t_{BUF} | SMBus Free Time Between Stop and Start Conditions | | | 1.3 | μs (min) |

(1) Typicals are at $T_A = 25^\circ\text{C}$ and represent most likely parametric norm.

(2) Limits are specified to AOQL (Average Outgoing Quality Level).

(3) The output rise time is measured from $(V_{IN(0)\text{max}} - 0.15\text{V})$ to $(V_{IN(1)\text{min}} + 0.15\text{V})$.

(4) The output fall time is measured from $(V_{IN(1)\text{min}} + 0.15\text{V})$ to $(V_{IN(0)\text{max}} - 0.15\text{V})$.

(5) Holding the SMBDAT and/or SMBCLK lines Low for a time interval greater than t_{TIMEOUT} will reset the LM95214's SMBus state machine, therefore setting SMBDAT and SMBCLK pins to a high impedance state.

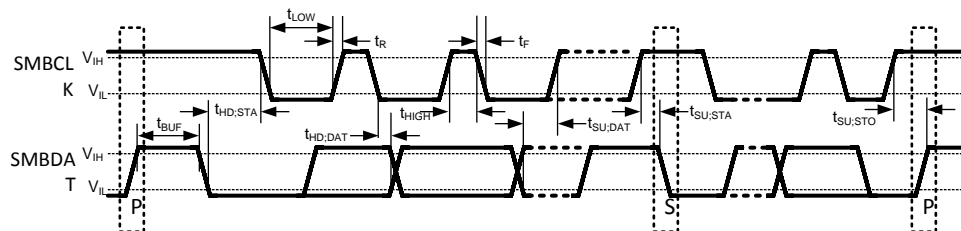
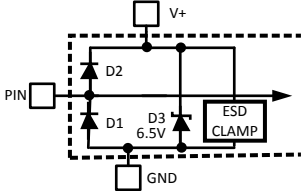
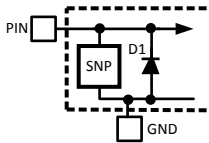


Figure 2. SMBus Communication

| Pin # | Label | Circuit | Circuits for Pin ESD Protection Structure |
|-------|-----------------|---------|--|
| 1 | NC | — |  <p>Circuit A</p> |
| 2 | V _{DD} | A | |
| 3 | D4+ | A | |
| 4 | D3+ | A | |
| 5 | D- | A | |
| 6 | D2+ | A | |
| 7 | D1+ | A | |
| 8 | GND | — | |
| 9 | A0 | B |  <p>Circuit B</p> |
| 10 | TCRIT1 | B | |
| 11 | TCRIT2 | B | |
| 12 | SMBDAT | B | |
| 13 | SMBCLK | B | |
| 14 | TCRIT2 | B | |

Typical Performance Characteristics

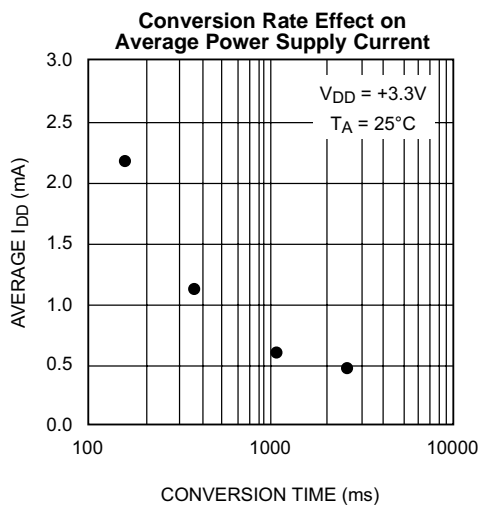


Figure 3.

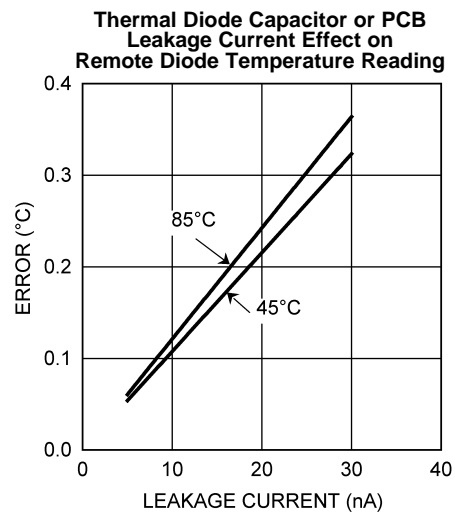


Figure 4.

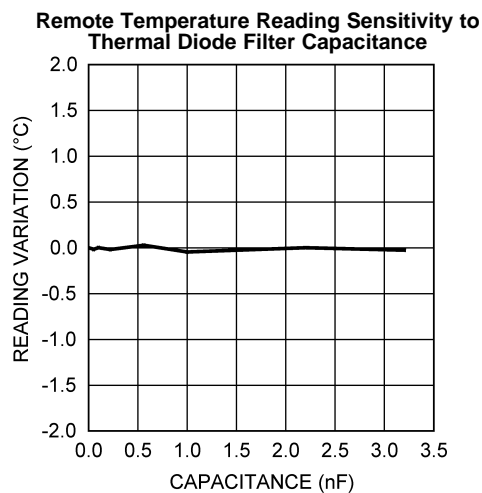


Figure 5.

FUNCTIONAL DESCRIPTION

The LM95214 is an 11-bit digital temperature sensor with a 2-wire System Management Bus (SMBus) interface that can monitor the temperature of four remote diodes as well as its own temperature. The LM95214 can be used to very accurately monitor the temperature of up to four external devices such as microprocessors, graphics processors or diode-connected 2N3904 transistor. Any device whose thermal diode can be modeled by an MMBT3904 transistor will work well with the LM95214.

The LM95214 reports temperature in two different formats for +127.875°C/–128°C range and 0°C/255°C range. The LM95214 has a Sigma-Delta ADC (Analog-to-Digital Converter) core which provides the first level of noise immunity. For improved performance in a noisy environment the LM95214 includes programmable digital filters for Remote Diode 1 and 2 temperature readings. When the digital filters are invoked the resolution for Remote Diode 1 and 2 readings increases to 0.03125°C. For maximum flexibility and best accuracy the LM95214 includes offset registers that allow calibration of other diode types.

Diode fault detection circuitry in the LM95214 can detect the absence or fault state of a remote diode: whether D+ is shorted to V_{DD}, D- or ground, or whether D+ is floating.

The LM95214 $\overline{\text{TCRIT1}}$, $\overline{\text{TCRIT2}}$ and $\overline{\text{TCRIT3}}$ active low outputs are triggered when any unmasked channel exceeds its corresponding programmable limit and can be used to shut down the system, to turn on the system fans or as a microcontroller interrupt function. The current status of the $\overline{\text{TCRIT1}}$, $\overline{\text{TCRIT2}}$ and $\overline{\text{TCRIT3}}$ pins can be read back from the status registers via the SMBus interface. Two of the remote channels have two separate limits each that control the $\overline{\text{TCRIT1}}$ and $\overline{\text{TCRIT2}}$ pins. The remaining two channels and the local channel each have one limit to control both the $\overline{\text{TCRIT1}}$ and $\overline{\text{TCRIT2}}$ pins. The $\overline{\text{TCRIT3}}$ pin shares the limits of the $\overline{\text{TCRIT2}}$ pin but allows for different masking options. All limits have a shared programmable hysteresis register.

Remote Diode 1 and 2 temperature channels have programmable digital filters while the other two remote temperature channels utilize a fault-queue in order to avoid false triggering the $\overline{\text{TCRIT}}$ pins.

The LM95214 has a three-level address pin to connect up to 3 devices to the same SMBus master. LM95214 also has programmable conversion rate register as well as a shutdown mode for power savings. One round of conversions can be triggered in shutdown mode by writing to the one-shot register through the SMBus interface. LM95214 can be programmed to turn off unused channels for more power savings.

The LM95214 register set has an 8-bit data structure and includes:

1. Temperature Value Registers with signed format
 - Most-Significant-Byte (MSB) and Least-Significant-Byte (LSB) Local Temperature
 - MSB and LSB Remote Temperature 1
 - MSB and LSB Remote Temperature 2
 - MSB and LSB Remote Temperature 3
 - MSB and LSB Remote Temperature 4
2. Temperature Value Registers with unsigned format
 - MSB and LSB Remote Temperature 1
 - MSB and LSB Remote Temperature 2
 - MSB and LSB Remote Temperature 3
 - MSB and LSB Remote Temperature 4
3. Diode Configuration Registers
 - Diode Model Select
 - Remote 1 Offset
 - Remote 2 Offset
 - Remote 3 Offset
 - Remote 4 Offset
4. General Configuration Registers
 - Configuration (Standby, Fault Queue enable for Remote 3 and 4; Conversion Rate)
 - Channel Conversion Enable
 - Filter Setting for Remote 1 and 2
 - 1-Shot

5. Status Registers

- Main Status Register (Busy bit, Not Ready, Status Register 1 to 4 Flags)
- Status 1 (diode fault)
- Status 2 (TCRIT1)
- Status 3 (TCRIT2)
- Status 4 (TCRIT3)

6. Mask Registers

- TCRIT1 Mask
- TCRIT2 Mask
- TCRIT3 Mask

7. Limit Registers

- Local Tcrit Limit
- Remote 1 Tcrit-1 Limit
- Remote 2 Tcrit-1 Limit
- Remote 3 Tcrit Limit
- Remote 4 Tcrit Limit
- Remote 1 Tcrit-2 and Tcrit-3 Limit
- Remote 2 Tcrit-2 and Tcrit-3 Limit
- Common Tcrit Hysteresis

8. Manufacturer ID Register

9. Revision ID Register

CONVERSION SEQUENCE

The LM95214 takes approximately 190 ms to convert the Local Temperature, Remote Temperatures 1 through 4, and to update all of its registers. These conversions for each thermal diode are addressed in a round robin sequence. Only during the conversion process the busy bit (D7) in Status register (02h) is high. The conversion rate may be modified by the Conversion Rate bits found in the Configuration Register (03h). When the conversion rate is modified a delay is inserted between each round of conversions, the actual time for each round remains at 190 ms (typical all channels enabled). The time a round takes depends on the number of channels that are on. Different conversion rates will cause the LM95214 to draw different amounts of average supply current as shown in [Figure 6](#). This curve assumes all the channels are on. If channels are turned off the average current will drop since the round robin time will decrease and the shutdown time will increase during each conversion interval.

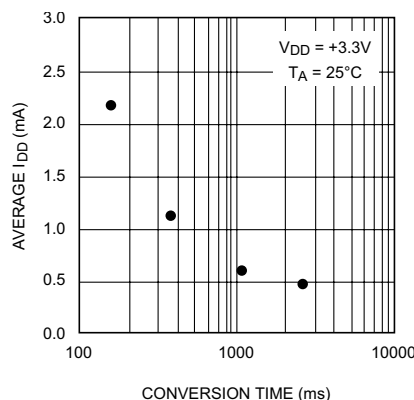


Figure 6. Conversion Rate Effect on Power Supply Current

POWER-ON-DEFAULT STATES

The LM95214 always powers up to these known default states. The LM95214 remains in these states until after the first conversion.

1. All Temperature readings set to 0°C until the end of the first conversion
2. Remote offset for all channels 0°C
3. Configuration: Active converting, Fault Queue enabled for Remote 3 and 4
4. Continuous conversion with all channels enabled, time = 1s
5. Enhanced digital filter enabled for Remote 1 and 2
6. Status Registers depends on state of thermal diode inputs
7. Local and Remote Temperature Limits for $\overline{\text{TCRIT1}}$, $\overline{\text{TCRIT2}}$ and $\overline{\text{TCRIT3}}$ outputs:

| Output Pin | Temperature Channel Limit | | | | |
|----------------------------|---------------------------|------------------|------------------|------------------|---------------|
| | Remote 4 (°C) | Remote 3 (°C) | Remote 2 (°C) | Remote 1 (°C) | Local (°C) |
| $\overline{\text{TCRIT1}}$ | Masked, 85 | Masked, 85 | 110 | 110 | Masked, 85 |
| $\overline{\text{TCRIT2}}$ | 85 | 85 | 85 | 85 | 85 |
| $\overline{\text{TCRIT3}}$ | 85 | 85 | Masked, 85 | Masked, 85 | Masked, 85 |

8. Manufacturers ID set to 01h
9. Revision ID set to 7Bh

SMBus INTERFACE

The LM95214 operates as a slave on the SMBus, so the SMBCLK line is an input and the SMBDAT line is bidirectional. The LM95214 never drives the SMBCLK line and it does not support clock stretching. According to SMBus specifications, the LM95214 has a 7-bit slave address. Three SMBus device address can be selected by connecting A0 (pin 6) to either Low, Mid-Supply or High voltages. The LM95214 has the following SMBus slave address:

| A0 Pin State | SMBus Device Address A[6:0] | |
|--------------|-----------------------------|----------|
| | Hex | Binary |
| Low | 18h | 001 1000 |
| Mid-Supply | 4Dh | 100 1101 |
| High | 4Eh | 100 1110 |

TEMPERATURE CONVERSION SEQUENCE

Each of the 5 temperature channels of LM95214 can be turned OFF independent from each other via the Channel Enable Register. Turning off unused channels will increase the conversion speed in the fastest conversion speed mode. If the slower conversion speed settings are used, disabling unused channels will reduce the average power consumption of LM95214.

Digital Filter

In order to suppress erroneous remote temperature readings due to noise as well as increase the resolution of the temperature, the LM95214 incorporates a digital filter for Remote 1 and 2 Temperature Channels. When a filter is enabled the filtered readings are used for the TCRIT comparisons. There are two possible digital filter settings that are enabled through the Filter Setting Register at register address 0Fh. The filter for each channel can be set according to the following table:

| R1F[1:0] or R2F[1:0] | | Filter Setting |
|----------------------|---|--|
| 0 | 0 | No Filter |
| 0 | 1 | Filter (equivalent to Level 2 filter of the LM86/LM89) |
| 1 | 0 | Reserved |
| 1 | 1 | Enhanced Filter (Filter with transient noise clipping) |

Figure 7, Figure 8, and Figure 9 describe the filter output in response to a step input and an impulse input.

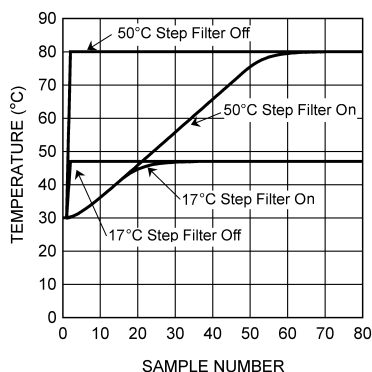


Figure 7. Seventeen and fifty degree step response

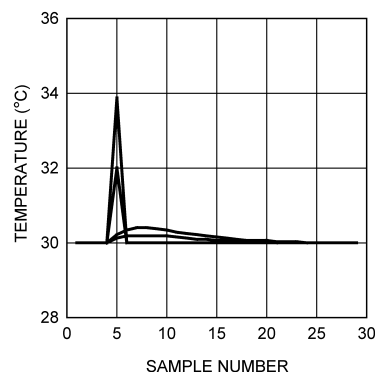


Figure 8. Impulse response with input transients less than 4°C

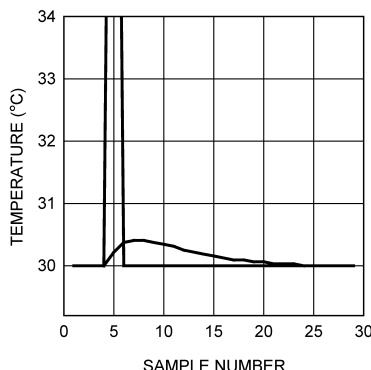


Figure 9. Impulse response with input transients great than 4°C

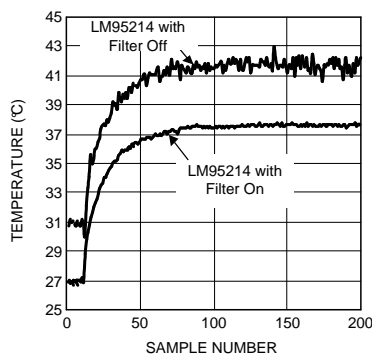


Figure 10. Digital Filter Response in a typical Intel processor on a 65 nm or 90 nm process. The filter curves were purposely offset for clarity.

Figure 10 shows the filter in use in a typical system. Note that the two curves have been purposely offset for clarity. Inserting the filter does not induce an offset as shown.

FAULT QUEUE

In order to suppress erroneous $\overline{\text{TCRIT1}}$, $\overline{\text{TCRIT2}}$ and $\overline{\text{TCRIT3}}$ triggering the LM95214 incorporates a Fault Queue for the unfiltered remote channels 3 and 4. The Fault Queue acts to ensure the remote temperature measurement of these channels is genuinely beyond the corresponding Tcrit limit by not triggering until three consecutive out of limit measurements have been made, see Figure 11 for an example. The Fault Queue defaults on upon power-up. The fault queue for channels 3 and 4 can be turned ON or OFF via bits 0 and 1 of the Configuration Register. When the fault queue is enabled, the $\overline{\text{TCRIT1}}$, $\overline{\text{TCRIT2}}$ and $\overline{\text{TCRIT3}}$ pins will be triggered if the temperature is above the Tcrit limit for 3 consecutive conversions and the corresponding mask bit is 0 in the TCRIT Mask registers. Similarly the temperature needs to be below the Tcrit limit minus the hysteresis value for three consecutive conversions for the $\overline{\text{TCRIT1}}$, $\overline{\text{TCRIT2}}$ and $\overline{\text{TCRIT3}}$ pins to deactivate.

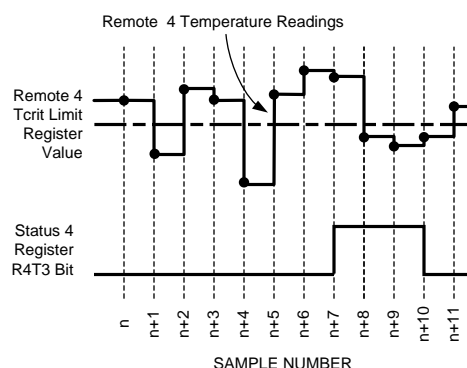


Figure 11. Fault Queue Response Diagram (with 0°C hysteresis)

TEMPERATURE DATA FORMAT

Temperature data can only be read from the Local and Remote Temperature value registers. The data format for all temperature values is left justified 16-bit word available in two 8-bit registers. Unused bits will always report "0". All temperature data is clamped and will not roll over when a temperature exceeds full-scale value.

Remote temperature data for all channels can be represented by an 11-bit, two's complement word or unsigned binary word with an LSB (Least Significant Bit) equal to 0.125°C.

Table 1. 11-bit, 2's complement (10-bit plus sign)

| Temperature | Digital Output | |
|-------------|---------------------|-------|
| | Binary | Hex |
| +125°C | 0111 1101 0000 0000 | 7D00h |
| +25°C | 0001 1001 0000 0000 | 1900h |
| +1°C | 0000 0001 0000 0000 | 0100h |
| +0.125°C | 0000 0000 0010 0000 | 0020h |
| 0°C | 0000 0000 0000 0000 | 0000h |
| -0.125°C | 1111 1111 1110 0000 | FFE0h |
| -1°C | 1111 1111 0000 0000 | FF00h |
| -25°C | 1110 0111 0000 0000 | E700h |
| -55°C | 1100 1001 0000 0000 | C900h |

Table 2. 11-bit, unsigned binary

| Temperature | Digital Output | |
|-------------|---------------------|-------|
| | Binary | Hex |
| +255.875°C | 1111 1111 1110 0000 | FFE0h |
| +255°C | 1111 1111 0000 0000 | FF00h |
| +201°C | 1100 1001 0000 0000 | C900h |
| +125°C | 0111 1101 0000 0000 | 7D00h |
| +25°C | 0001 1001 0000 0000 | 1900h |
| +1°C | 0000 0001 0000 0000 | 0100h |
| +0.125°C | 0000 0000 0010 0000 | 0020h |
| 0°C | 0000 0000 0000 0000 | 0000h |

When the digital filter is enabled on Remote 1 and 2 channels temperature data is represented by a 13-bit unsigned binary or 12-bit plus sign (two's complement) word with an LSb equal to 0.03125°C.

Table 3. 13-bit, 2's complement (12-bit plus sign)

| Temperature | Digital Output | |
|-------------|---------------------|-------|
| | Binary | Hex |
| +125°C | 0111 1101 0000 0000 | 7D00h |
| +25°C | 0001 1001 0000 0000 | 1900h |
| +1°C | 0000 0001 0000 0000 | 0100h |
| +0.03125°C | 0000 0000 0000 1000 | 0008h |
| 0°C | 0000 0000 0000 0000 | 0000h |
| -0.03125°C | 1111 1111 1111 1000 | FFF8h |
| -1°C | 1111 1111 0000 0000 | FF00h |
| -25°C | 1110 0111 0000 0000 | E700h |
| -55°C | 1100 1001 0000 0000 | C900h |

Table 4. 13-bit, unsigned binary

| Temperature | Digital Output | |
|-------------|---------------------|-------|
| | Binary | Hex |
| +255.875°C | 1111 1111 1110 0000 | FFE0h |
| +255°C | 1111 1111 0000 0000 | FF00h |
| +201°C | 1100 1001 0000 0000 | C900h |
| +125°C | 0111 1101 0000 0000 | 7D00h |
| +25°C | 0001 1001 0000 0000 | 1900h |
| +1°C | 0000 0001 0000 0000 | 0100h |
| +0.03125°C | 0000 0000 0000 1000 | 0008h |
| 0°C | 0000 0000 0000 0000 | 0000h |

Local Temperature data is only represented by an 11-bit, two's complement, word with an LSb equal to 0.125°C.

Table 5. 11-bit, 2's complement (10-bit plus sign)

| Temperature | Digital Output | |
|-------------|---------------------|-------|
| | Binary | Hex |
| +125°C | 0111 1101 0000 0000 | 7D00h |
| +25°C | 0001 1001 0000 0000 | 1900h |
| +1°C | 0000 0001 0000 0000 | 0100h |
| +0.125°C | 0000 0000 0010 0000 | 0020h |
| 0°C | 0000 0000 0000 0000 | 0000h |
| -0.125°C | 1111 1111 1110 0000 | FFE0h |
| -1°C | 1111 1111 0000 0000 | FF00h |
| -25°C | 1110 0111 0000 0000 | E700h |
| -55°C | 1100 1001 0000 0000 | C900h |

SMBDAT OPEN-DRAIN OUTPUT

The SMBDAT output is an open-drain output and does not have internal pull-ups. A "high" level will not be observed on this pin until pull-up current is provided by some external source, typically a pull-up resistor. Choice of resistor value depends on many system factors but, in general, the pull-up resistor should be as large as possible without effecting the SMBus desired data rate. This will minimize any internal temperature reading errors due to internal heating of the LM95214. The maximum resistance of the pull-up to provide a 2.1V high level, based on LM95214 specification for High Level Output Current with the supply voltage at 3.0V, is 82 kΩ (5%) or 88.7 kΩ (1%).

TCRIT1, TCRIT2, and TCRIT3 OUTPUTS

The LM95214's $\overline{\text{TCRIT}}$ pins are active-low open-drain outputs and do not include internal pull-up resistors. A "high" level will not be observed on these pins until pull-up current is provided by some external source, typically a pull-up resistor. Choice of resistor value depends on many system factors but, in general, the pull-up resistor should be as large as possible without effecting the performance of the device receiving the signal. This will minimize any internal temperature reading errors due to internal heating of the LM95214. The maximum resistance of the pull-up to provide a 2.1V high level, based on LM95214 specification for High Level Output Current with the supply voltage at 3.0V, is 82 kΩ (5%) or 88.7 kΩ (1%). The three $\overline{\text{TCRIT}}$ pins can each sink 6 mA of current and still ensured a "Logic Low" output voltage of 0.4V. If all three pins are set at maximum current this will cause a power dissipation of 7.2 mW. This power dissipation combined with a thermal resistance of 77.8°C/W will cause the LM95214's junction temperature to rise approximately 0.6°C and thus cause the Local temperature reading to shift. This can only be cancelled out if the environment that the LM95214 is enclosed in has stable and controlled air flow over the LM95214, as airflow can cause the thermal resistance to change dramatically.

Tcrit LIMITS AND $\overline{\text{TCRIT}}$ OUTPUTS

Figure 12 describes a simplified diagram of the temperature comparison and status register logic. Figure 13, Figure 14, and Figure 15 describe simplified logic diagrams of the circuitry associated with the status registers, mask registers and the $\overline{\text{TCRIT}}$ output pins.

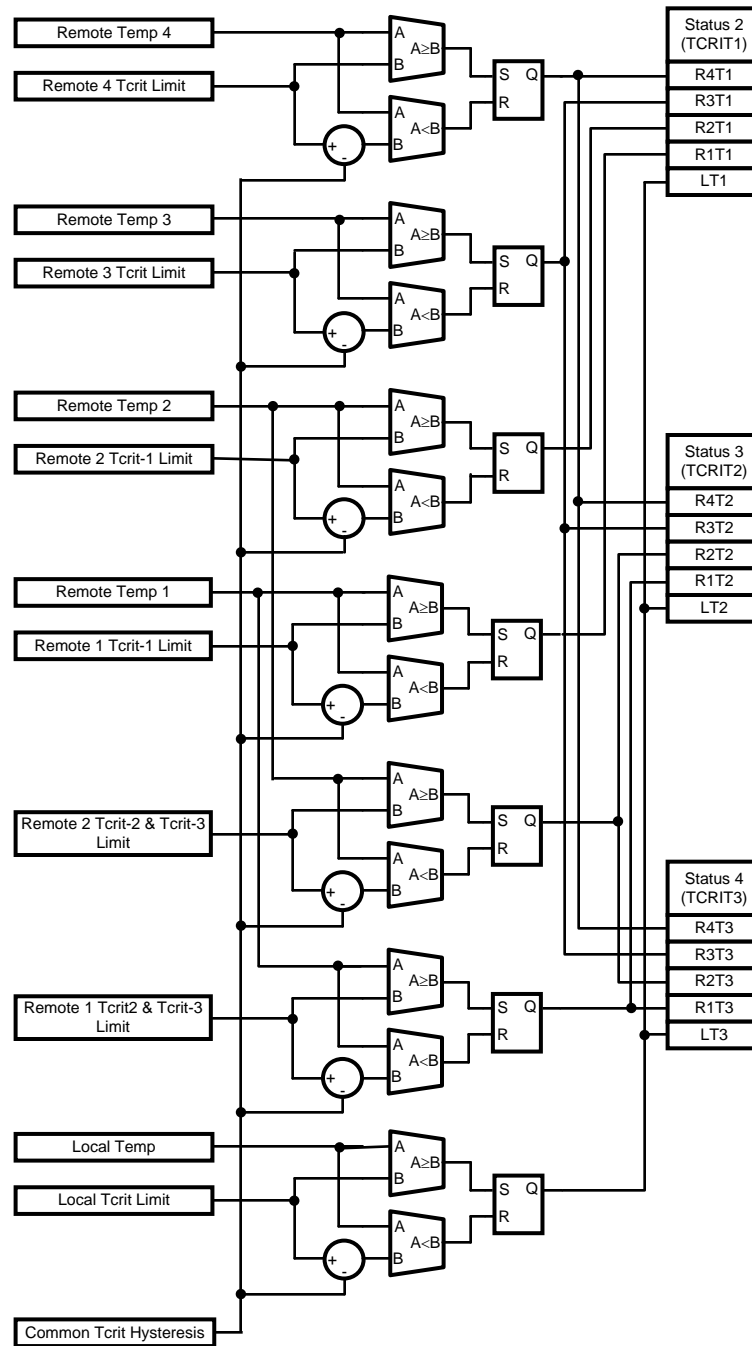


Figure 12. Temperature Comparison Logic and Status Register Simplified Diagram

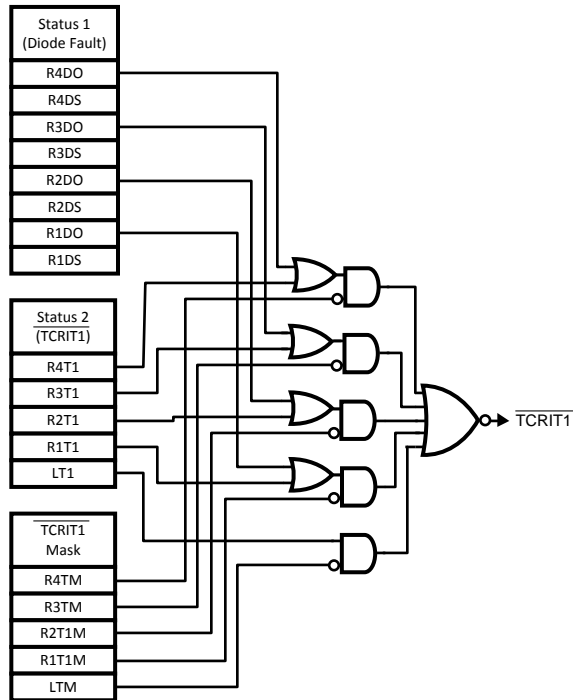


Figure 13. $\overline{\text{TCRIT1}}$ Mask Register, Status Register 1 and 2, and $\overline{\text{TCRIT1}}$ output logic diagram

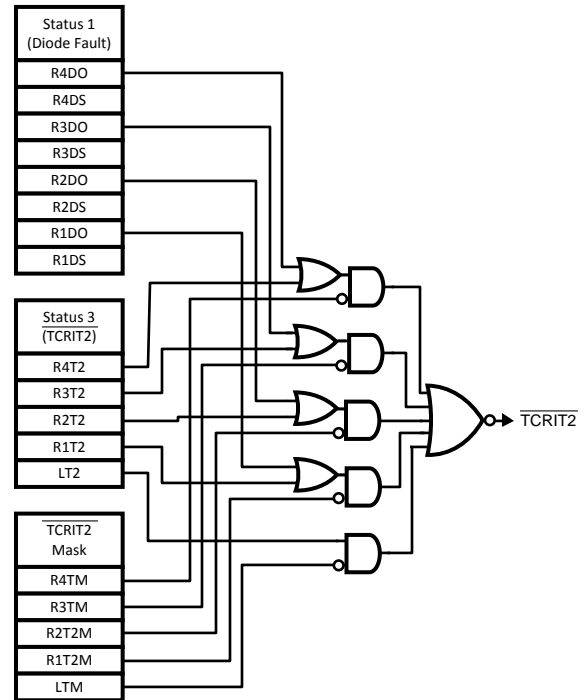


Figure 14. $\overline{\text{TCRIT2}}$ Mask Register, Status Register 1 and 3, and $\overline{\text{TCRIT2}}$ output logic diagram

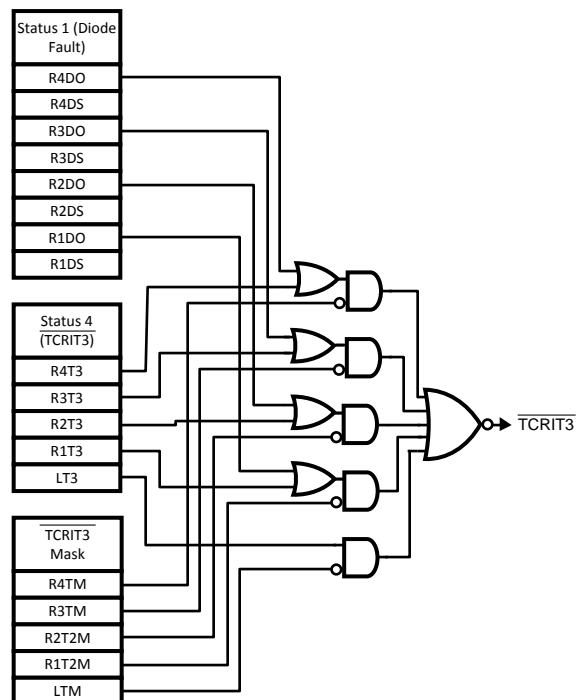


Figure 15. $\overline{\text{TCRIT3}}$ Mask Register, Status Register 1 and 4, and $\overline{\text{TCRIT3}}$ output logic diagram

If enabled, local temperature is compared to the user programmable Local Tcrit Limit Register (Default Value = 85°C). The result of this comparison is stored in Status Register 2, Status Register 3 and Status Register 4 (see [Figure 12](#)). The comparison result can trigger $\overline{\text{TCRIT1}}$ pin, $\overline{\text{TCRIT2}}$ pin or $\overline{\text{TCRIT3}}$ pin depending on the settings in the TCRIT1 Mask, TCRIT2 Mask and TCRIT3 Mask Registers (see [Figure 13](#), [Figure 14](#), and [Figure 15](#)). The comparison result can also be read back from the Status Register 2, Status Register 3 and Status Register 4.

If enabled, remote temperature 1 is compared to the user programmable Remote 1 Tcrit-1 Limit Register (Default Value 110°C) and Remote 1 Tcrit-2 Limit Register (Default Value = 85°C). The result of this comparison is stored in Status Register 2, Status Register 3 and Status Register 4 (see Figure 12). The comparison result can trigger TCRIT1 pin, TCRIT2 pin or TCRIT3 pin depending on the settings in the TCRIT1 Mask, TCRIT2 Mask and TCRIT3 Mask Registers (see Figure 13, Figure 14, and Figure 15). The comparison result can also be read back from the Status Register 2, Status Register 3 and Status Register 4. The remote temperature 2 operates in a similar manner to remote temperature 1 using its associated user programmable limit registers: Remote 2 Tcrit-1 Limit Register (Default Value 110°C) and Remote 2 Tcrit-2 Limit Register (Default Value = 85°C). When enabled, the remote temperature 3 is compared to the user programmable Remote 3 Tcrit Limit Register (Default Value 85°C). The comparison result can trigger TCRIT1 pin, TCRIT2 pin or TCRIT3 pin depending on the settings in the TCRIT1 Mask, TCRIT2 Mask and TCRIT3 Mask Registers. The comparison result can also be read back from the Status Register 2, Status Register 3 and Status Register 4. The remote temperature 4 operates in a similar manner to remote temperature 3 using its associated user programmable limit register: Remote 4 Tcrit Limit Register (Default Value 85°C).

Table 6. Limit assignments for each TCRIT output pin:

| | TCRIT1 | TCRIT2 | TCRIT3 |
|-----------------|------------------------|------------------------|------------------------|
| Remote 4 | Remote 4 Tcrit Limit | Remote 4 Tcrit Limit | Remote 4 Tcrit Limit |
| Remote 3 | Remote 3 Tcrit Limit | Remote 3 Tcrit Limit | Remote 3 Tcrit Limit |
| Remote 2 | Remote 2 Tcrit-1 Limit | Remote 2 Tcrit-2 Limit | Remote 2 Tcrit-2 Limit |
| Remote 1 | Remote 1 Tcrit-1 Limit | Remote 1 Tcrit-2 Limit | Remote 1 Tcrit-2 Limit |
| Local | Local Tcrit Limit | Local Tcrit Limit | Local Tcrit Limit |

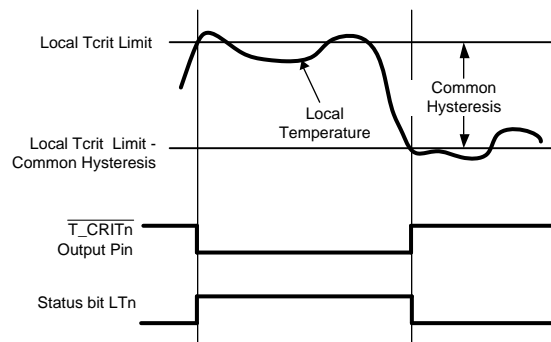


Figure 16. TCRIT response diagram (masking options not included)

The TCRIT response diagram of Figure 16 shows the local temperature interaction with the Tcrit limit and hysteresis value. As can be seen in the diagram when the local temperature exceeds the Tcrit limit register value the LTn Status bit is set and the T_CRITn output(s) is/are activated. The Status bit(s) and outputs are not deactivated until the temperature goes below the value calculated by subtracting the Common Hysteresis value programmed from the limit. This diagram mainly shows an example function of the hysteresis and is not meant to show complete function of the possible settings and options of all the TCRIT outputs and limit values.

DIODE FAULT DETECTION

The LM95214 is equipped with operational circuitry designed to detect fault conditions concerning the remote diodes. In the event that the D+ pin is detected as shorted to GND, D-, V_{DD} or D+ is floating, the Remote Temperature reading is -128.000°C if signed format is selected and 0°C if unsigned format is selected. In addition, the appropriate status register bits RD1M or RD2M (D1 or D0) are set.

COMMUNICATING with the LM95214

The data registers in the LM95214 are selected by the Command Register. At power-up the Command Register is set to "00", the location for the Read Local Temperature Register. The Command Register latches the last location it was set to. Each data register in the LM95214 falls into one of three types of user accessibility:

1. Read only
2. Write only
3. Write/Read same address

A **Write** to the LM95214 will always include the address byte and the command byte. A write to any register requires one data byte.

Reading the LM95214 can take place either of two ways:

1. If the location latched in the Command Register is correct (most of the time it is expected that the Command Register will point to one of the Read Temperature Registers because that will be the data most frequently read from the LM95214), then the read can simply consist of an address byte, followed by retrieving the data byte.
2. If the Command Register needs to be set, then an address byte, command byte, repeat start, and another address byte will accomplish a read.

The data byte has the most significant bit first. At the end of a read, the LM95214 can accept either acknowledge or No Acknowledge from the Master (No Acknowledge is typically used as a signal for the slave that the Master has read its last byte). It takes the LM95214 190 ms (typical, all channels enabled) to measure the temperature of the remote diodes and internal diode. When retrieving all 11 bits from a previous remote diode temperature measurement, the master must insure that all 11 bits are from the same temperature conversion. This may be achieved by reading the MSB register first. The LSB will be locked after the MSB is read. The LSB will be unlocked after being read. If the user reads MSBs consecutively, each time the MSB is read, the LSB associated with that temperature will be locked in and override the previous LSB value locked-in.

SMBus Timing Diagrams

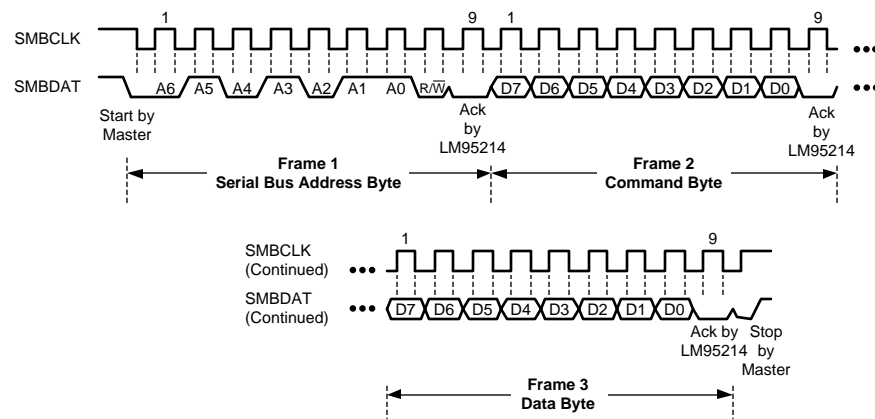


Figure 17. Serial Bus Write to the internal Command Register followed by a the Data Byte

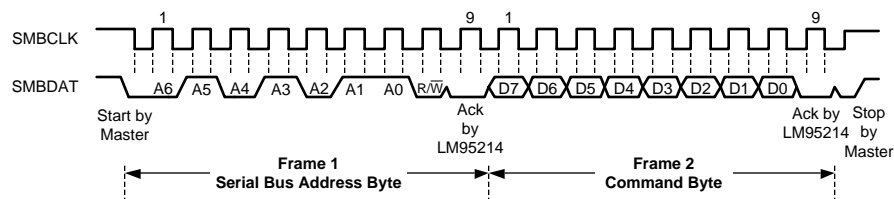


Figure 18. Serial Bus Write to the Internal Command Register

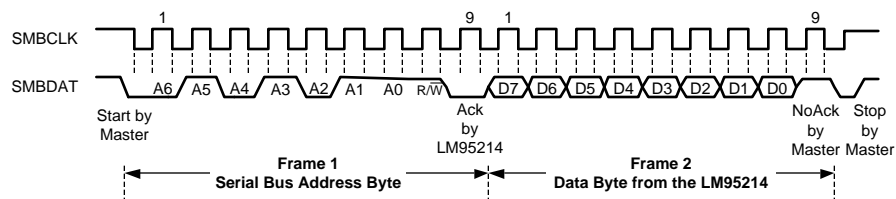


Figure 19. Serial Bus Read from a Register with the Internal Command Register preset to desired value

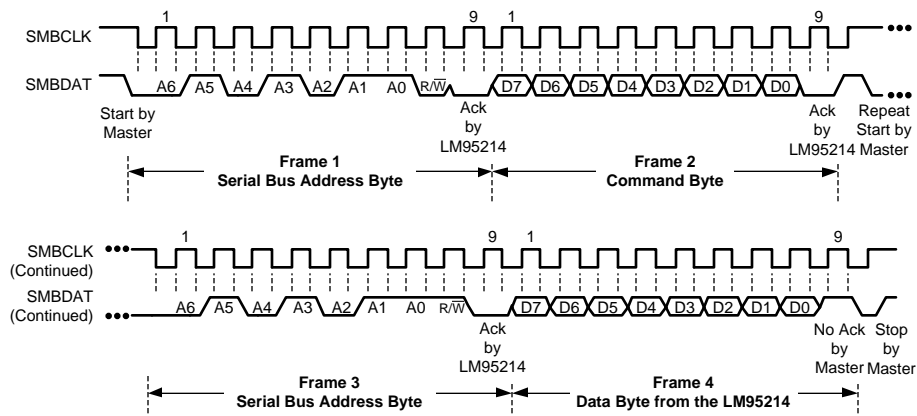


Figure 20. Serial Bus Write followed by a Repeat Start and Immediate Read

SERIAL INTERFACE RESET

In the event that the SMBus Master is RESET while the LM95214 is transmitting on the SMBDAT line, the LM95214 must be returned to a known state in the communication protocol. This may be done in one of two ways:

1. When SMBDAT is LOW, the LM95214 SMBus state machine resets to the SMBus idle state if either SMBDAT or SMBCLK are held low for more than 35ms ($t_{TIMEOUT}$). Note that according to SMBus specification 2.0 all devices are to timeout when either the SMBCLK or SMBDAT lines are held low for 25-35ms. Therefore, to insure a timeout of all devices on the bus the SMBCLK or SMBDAT lines must be held low for at least 35ms.
2. When SMBDAT is HIGH, have the master initiate an SMBus start. The LM95214 will respond properly to an SMBus start condition at any point during the communication. After the start the LM95214 will expect an SMBus Address address byte.

ONE-SHOT CONVERSION

The One-Shot register is used to initiate a round of conversions and comparisons when the device is in standby mode, after which the device returns to standby. This is not a data register and it is the write operation that causes the one-shot conversion. The data written to this address is irrelevant and is not stored. A zero will always be read from this register. All the channels that are enabled in the Channel Enable Register will be converted once and the TCRIT1, TCRIT2 and TCRIT3 pins will reflect the comparison results based on this round of conversion results of the channels that are not masked.

LM95214 Registers

Command register selects which registers will be read from or written to. Data for this register should be transmitted during the Command Byte of the SMBus write communication.

| P7 | P6 | P5 | P4 | P3 | P2 | P1 | P0 |
|--------------|----|----|----|----|----|----|----|
| Command Byte | | | | | | | |

P0-P7: Command

Table 7. Register Summary

| Register Name | Command Byte (Hex) | Read/Write | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 | POR Default (Hex) |
|--|--------------------|------------|------|------|------|------|------|------|------|------|-------------------|
| Local Temp MSB | 0x10 | RO | SIGN | 64 | 32 | 16 | 8 | 4 | 2 | 1 | – |
| Local Temp LSB | 0x20 | RO | 1/2 | 1/4 | 1/8 | 0 | 0 | 0 | 0 | 0 | – |
| Remote Temp 1 MSB – Signed | 0x11 | RO | SIGN | 64 | 32 | 16 | 8 | 4 | 2 | 1 | – |
| Remote Temp 1 LSB – Signed, Digital Filter Off | 0x21 | RO | 1/2 | 1/4 | 1/8 | 0 | 0 | 0 | 0 | 0 | – |
| Remote Temp 1 LSB – Signed, Digital Filter On | | | | | | 1/16 | 1/32 | | | | |
| Remote Temp 2 MSB – Signed | 0x12 | RO | SIGN | 64 | 32 | 16 | 8 | 4 | 2 | 1 | – |
| Remote Temp 2 LSB – Signed, Digital Filter Off | 0x22 | RO | 1/2 | 1/4 | 1/8 | 0 | 0 | 0 | 0 | 0 | – |
| Remote Temp 2 LSB – Signed, Digital Filter On | | | | | | 1/16 | 1/32 | | | | |
| Remote Temp 3 MSB – Signed | 0x13 | RO | SIGN | 64 | 32 | 16 | 8 | 4 | 2 | 1 | – |
| Remote Temp 3 LSB – Signed | 0x23 | RO | 1/2 | 1/4 | 1/8 | 0 | 0 | 0 | 0 | 0 | – |
| Remote Temp 4 MSB – Signed | 0x14 | RO | SIGN | 64 | 32 | 16 | 8 | 4 | 2 | 0 | – |
| Remote Temp 4 LSB – Signed | 0x24 | RO | 1/2 | 1/4 | 1/8 | 0 | 0 | 0 | 0 | 0 | – |
| Remote Temp 1 MSB – Unsigned | 0x19 | RO | 128 | 64 | 32 | 16 | 8 | 4 | 2 | 1 | – |
| Remote Temp 1 LSB – Unsigned, Digital Filter Off | 0x29 | RO | 1/2 | 1/4 | 1/8 | 0 | 0 | 0 | 0 | 0 | – |
| Remote Temp 1 LSB – Unsigned, Digital Filter On | | | | | | 1/16 | 1/32 | | | | |
| Remote Temp 2 MSB – Unsigned | 0x1A | RO | 128 | 64 | 32 | 16 | 8 | 4 | 2 | 1 | – |
| Remote Temp 2 LSB – Unsigned, Digital Filter Off | 0x2A | RO | 1/2 | 1/4 | 1/8 | 0 | 0 | 0 | 0 | 0 | – |
| Remote Temp 2 LSB – Unsigned, Digital Filter On | | | | | | 1/16 | 1/32 | | | | |
| Remote Temp 3 MSB – Unsigned | 0x1B | RO | 128 | 64 | 32 | 16 | 8 | 4 | 2 | 1 | – |
| Remote Temp 3 LSB – Unsigned | 0x2B | RO | 1/2 | 1/4 | 1/8 | 0 | 0 | 0 | 0 | 0 | – |
| Remote Temp 4 MSB – Unsigned | 0x1C | RO | 128 | 64 | 32 | 16 | 8 | 4 | 2 | 1 | – |
| Remote Temp 4 LSB – Unsigned | 0x2C | RO | 1/2 | 1/4 | 1/8 | 0 | 0 | 0 | 0 | 0 | – |
| Remote 1 Offset | 0x31 | R/W | SIGN | 32 | 16 | 8 | 4 | 2 | 1 | 1/2 | 0x00 |
| Remote 2 Offset | 0x32 | R/W | SIGN | 32 | 16 | 8 | 4 | 2 | 1 | 1/2 | 0x00 |
| Remote 3 Offset | 0x33 | R/W | SIGN | 32 | 16 | 8 | 4 | 2 | 1 | 1/2 | 0x00 |
| Remote 4 Offset | 0x34 | R/W | SIGN | 32 | 16 | 8 | 4 | 2 | 1 | 1/2 | 0x00 |
| Configuration | 0x03 | R/W | – | STBY | – | – | – | – | R4QE | R3QE | 0x03 |
| Conversion Rate | 0x04 | R/W | – | – | – | – | – | – | CR1 | CR0 | 0x02 |
| Channel Conversion Enable | 0x05 | R/W | – | – | – | R4CE | R3CE | R2CE | R1CE | LCE | 0x1F |
| Filter Setting | 0x06 | R/W | – | – | – | – | R2F1 | R2F0 | R1F1 | R1F0 | 0x0F |
| 1-shot | 0x0F | WO | – | – | – | – | – | – | – | – | – |
| Common Status Register | 0x02 | RO | BUSY | NR | – | – | SR4F | SR3F | SR2F | SR1F | 0x00 |
| Status 1 (Diode Fault) | 0x07 | RO | R4DO | R4DS | R3DO | R3DS | R2DO | R2DS | R1DO | R1DS | – |
| Status 2 ($\overline{\text{TCRIT1}}$) | 0x08 | RO | – | – | – | R4T1 | R3T1 | R2T1 | R1T1 | LT1 | – |
| Status 3 ($\overline{\text{TCRIT2}}$) | 0x09 | RO | – | – | – | R4T2 | R3T2 | R2T2 | R1T2 | LT2 | – |
| Status 4 ($\overline{\text{TCRIT3}}$) | 0x0A | RO | – | – | – | R4T3 | R3T3 | R2T3 | R1T3 | LT3 | – |

Table 7. Register Summary (continued)

| Register Name | Command Byte (Hex) | Read/Write | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 | POR Default (Hex) |
|------------------------------------|--------------------|------------|-----|----|----|------|------|-------|-------|-----|-------------------|
| TCRIT1 Mask | 0x0C | R/W | – | – | – | R4TM | R3TM | R2T1M | R1T1M | LTM | 0x19 |
| TCRIT2 Mask | 0x0D | R/W | – | – | – | R4TM | R3TM | R2T2M | R1T2M | LTM | 0x00 |
| TCRIT3 Mask | 0x0E | R/W | – | – | – | R4TM | R3TM | R2T2M | R1T2M | LTM | 0x07 |
| Local Tcrit Limit | 0x40 | R/W | 0 | 64 | 32 | 16 | 8 | 4 | 2 | 1 | 0x55 |
| Remote 1 Tcrit-1 Limit | 0x41 | R/W | 128 | 64 | 32 | 16 | 8 | 4 | 2 | 1 | 0x6E |
| Remote 2 Tcrit-1 Limit | 0x42 | R/W | 128 | 64 | 32 | 16 | 8 | 4 | 2 | 1 | 0x6E |
| Remote 3 Tcrit Limit | 0x43 | R/W | 128 | 64 | 32 | 16 | 8 | 4 | 2 | 1 | 0x55 |
| Remote 4 Tcrit Limit | 0x44 | R/W | 128 | 64 | 32 | 16 | 8 | 4 | 2 | 1 | 0x55 |
| Remote 1 Tcrit-2 and Tcrit-3 Limit | 0x49 | R/W | 128 | 64 | 32 | 16 | 8 | 4 | 2 | 1 | 0x55 |
| Remote 2 Tcrit-2 and Tcrit-3 Limit | 0x4A | R/W | 128 | 64 | 32 | 16 | 8 | 4 | 2 | 1 | 0x55 |
| Common Tcrit Hysteresis | 0x5A | R/W | 0 | 0 | 0 | 16 | 8 | 4 | 2 | 1 | 0x0A |
| Manufacturer ID | 0xFE | RO | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 1 | 0x01 |
| Revision ID | 0xFF | RO | 0 | 1 | 1 | 1 | 1 | 0 | 1 | 1 | 0x7B |

VALUE REGISTERS

For data synchronization purposes, the MSB register should be read first if the user wants to read both MSB and LSB registers. The LSB will be locked after the MSB is read. The LSB will be unlocked after being read. If the user reads MSBs consecutively, each time the MSB is read, the LSB associated with that temperature will be locked in and override the previous LSB value locked-in

Local Value Registers

| Register Name | Command Byte (Hex) | Read/Write | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 | POR Default (Hex) |
|----------------|--------------------|------------|------|-----|-----|----|----|----|----|----|-------------------|
| Local Temp MSB | 0x10 | RO | SIGN | 64 | 32 | 16 | 8 | 4 | 2 | 1 | – |
| Local Temp LSB | 0x20 | RO | 1/2 | 1/4 | 1/8 | 0 | 0 | 0 | 0 | 0 | – |

| Bit(s) | Bit Name | Read/Write | Description |
|--------|----------|------------|-----------------|
| 7 | SIGN | RO | Sign bit |
| 6 | 64 | RO | bit weight 64°C |
| 5 | 32 | RO | bit weight 32°C |
| 4 | 16 | RO | bit weight 16°C |
| 3 | 8 | RO | bit weight 8°C |
| 2 | 4 | RO | bit weight 4°C |
| 1 | 2 | RO | bit weight 2°C |
| 0 | 1 | RO | bit weight 1°C |

The Local temperature MSB value register range is +127°C to –128°C. The value programmed in this register is used to determine a local temperature error event.

| Bit(s) | Bit Name | Read/Write | Description |
|--------|----------|------------|---------------------------------------|
| 7 | 1/2 | RO | bit weight 1/2°C (0.5°C) |
| 6 | 1/4 | RO | bit weight 1/4°C (0.25°C) |
| 5 | 1/8 | RO | bit weight 1/8°C (0.125°C) |
| 4-0 | 0 | RO | Reserved – will report "0" when read. |

The Local Limit register range is 0°C to 127°C. The value programmed in this register is used to determine a local temperature error event.

Remote Temperature Value Registers with Signed Format

| Register Name | Command Byte (Hex) | Read/Write | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 | POR Default (Hex) |
|--|--------------------|------------|------|-----|------|------|----|----|----|----|-------------------|
| Remote Temp 1 MSB – Signed | 0x11 | RO | SIGN | 64 | 32 | 16 | 8 | 4 | 2 | 1 | – |
| Remote Temp 1 LSB – Signed, Digital Filter Off | 0x21 | RO | 1/2 | 1/8 | 0 | 0 | 0 | 0 | 0 | 0 | – |
| Remote Temp 1 LSB – Signed, Digital Filter On | | | | | 1/16 | 1/32 | | | | | |
| Remote Temp 2 MSB – Signed | 0x12 | RO | SIGN | 64 | 32 | 16 | 8 | 4 | 2 | 1 | – |
| Remote Temp 2 LSB – Signed, Digital Filter Off | 0x22 | RO | 1/2 | 1/8 | 0 | 0 | 0 | 0 | 0 | 0 | – |
| Remote Temp 2 LSB – Signed, Digital Filter On | | | | | 1/16 | 1/32 | | | | | |
| Remote Temp 3 MSB – Signed | 0x13 | RO | SIGN | 64 | 32 | 16 | 8 | 4 | 2 | 1 | – |
| Remote Temp 3 LSB – Signed | 0x23 | RO | 1/2 | 1/8 | 0 | 0 | 0 | 0 | 0 | 0 | – |
| Remote Temp 4 MSB – Signed | 0x14 | RO | SIGN | 64 | 32 | 16 | 8 | 4 | 2 | 0 | – |
| Remote Temp 4 LSB – Signed | 0x24 | RO | 1/2 | 1/8 | 0 | 0 | 0 | 0 | 0 | 0 | – |

The Local temperature MSB value register range is +127°C to –128°C. The value programmed in this register is used to determine a local temperature error event.

| Bit(s) | Bit Name | Read/Write | Description |
|--------|----------|------------|-----------------|
| 7 | SIGN | RO | Sign bit |
| 6 | 64 | RO | bit weight 64°C |
| 5 | 32 | RO | bit weight 32°C |
| 4 | 16 | RO | bit weight 16°C |
| 3 | 8 | RO | bit weight 8°C |
| 2 | 4 | RO | bit weight 4°C |
| 1 | 2 | RO | bit weight 2°C |
| 0 | 1 | RO | bit weight 1°C |

| Bit(s) | Bit Name | Read/Write | Description |
|--------|-----------|------------|---|
| 7 | 1/2 | RO | bit weight 1/2°C (0.5°C) |
| 6 | 1/4 | RO | bit weight 1/4°C (0.25°C) |
| 5 | 1/8 | RO | bit weight 1/8°C (0.125°C) |
| 4 | 0 or 1/16 | RO | When the digital filter is disabled this bit will always read "0". When the digital filter is enabled this bit will report 1/16°C (0.0625°C) bit state. |
| 3 | 0 or 1/32 | RO | When the digital filter is disabled this bit will always read "0". When the digital filter is enabled this bit will report 1/32°C (0.03125°C) bit state. |
| 2-0 | 0 | RO | Reserved – will report "0" when read. |

Remote Temperature Value Registers with Unsigned Format

| Register Name | Command Byte (Hex) | Read/Write | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 | POR Default (Hex) |
|--|--------------------|------------|-----|-----|------|------|----|----|----|----|-------------------|
| Remote Temp 1 MSB – Unsigned | 0x19 | RO | 128 | 64 | 32 | 16 | 8 | 4 | 2 | 1 | – |
| Remote Temp 1 LSB – Unsigned, Digital Filter Off | 0x29 | RO | 1/2 | 1/8 | 0 | 0 | 0 | 0 | 0 | 0 | – |
| Remote Temp 1 LSB – Unsigned, Digital Filter On | | | | | 1/16 | 1/32 | | | | | |
| Remote Temp 2 MSB – Unsigned | 0x1A | RO | 128 | 64 | 32 | 16 | 8 | 4 | 2 | 1 | – |
| Remote Temp 2 LSB – Unsigned, Digital Filter Off | 0x2A | RO | 1/2 | 1/8 | 0 | 0 | 0 | 0 | 0 | 0 | – |
| Remote Temp 2 LSB – Unsigned, Digital Filter On | | | | | 1/16 | 1/32 | | | | | |
| Remote Temp 3 MSB – Unsigned | 0x1B | RO | 128 | 64 | 32 | 16 | 8 | 4 | 2 | 1 | – |
| Remote Temp 3 LSB – Unsigned | 0x2B | RO | 1/2 | 1/8 | 0 | 0 | 0 | 0 | 0 | 0 | – |
| Remote Temp 4 MSB – Unsigned | 0x1C | RO | 128 | 64 | 32 | 16 | 8 | 4 | 2 | 1 | – |
| Remote Temp 4 LSB – Unsigned | 0x2C | RO | 1/2 | 1/8 | 0 | 0 | 0 | 0 | 0 | 0 | – |

| Bit(s) | Bit Name | Read/Write | Description |
|--------|----------|------------|------------------|
| 7 | SIGN | RO | bit weight 128°C |
| 6 | 64 | RO | bit weight 64°C |
| 5 | 32 | RO | bit weight 32°C |
| 4 | 16 | RO | bit weight 16°C |
| 3 | 8 | RO | bit weight 8°C |
| 2 | 4 | RO | bit weight 4°C |
| 1 | 2 | RO | bit weight 2°C |
| 0 | 1 | RO | bit weight 1°C |

| Bit(s) | Bit Name | Read/Write | Description |
|--------|-----------|------------|---|
| 7 | 1/2 | RO | bit weight 1/2°C (0.5°C) |
| 6 | 1/4 | RO | bit weight 1/4°C (0.25°C) |
| 5 | 1/8 | RO | bit weight 1/8°C (0.125°C) |
| 4 | 0 or 1/16 | RO | When the digital filter is disabled this bit will always read "0". When the digital filter is enabled this bit will report 1/16°C (0.0625°C) bit state. |
| 3 | 0 or 1/32 | RO | When the digital filter is disabled this bit will always read "0". When the digital filter is enabled this bit will report 1/32°C (0.03125°C) bit state. |
| 2-0 | 0 | RO | Reserved – will report "0" when read. |

DIODE CONFIGURATION REGISTER

Remote 1-4 Offset

| Register Name | Command Byte (Hex) | Read/Write | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 | POR Default (Hex) |
|-----------------|--------------------|------------|------|----|----|----|----|----|----|-----|-------------------|
| Remote 1 Offset | 0x31 | R/W | SIGN | 32 | 16 | 8 | 4 | 2 | 1 | 1/2 | 0x00 |
| Remote 2 Offset | 0x32 | R/W | SIGN | 32 | 16 | 8 | 4 | 2 | 1 | 1/2 | 0x00 |
| Remote 3 Offset | 0x33 | R/W | SIGN | 32 | 16 | 8 | 4 | 2 | 1 | 1/2 | 0x00 |
| Remote 4 Offset | 0x34 | R/W | SIGN | 32 | 16 | 8 | 4 | 2 | 1 | 1/2 | 0x00 |

| Bit(s) | Bit Name | Read/Write | Description |
|--------|----------|------------|--------------------------|
| 7 | SIGN | R/W | Sign bit |
| 6 | 32 | R/W | bit weight 32°C |
| 5 | 16 | R/W | bit weight 16°C |
| 4 | 8 | R/W | bit weight 8°C |
| 3 | 4 | R/W | bit weight 4°C |
| 2 | 2 | R/W | bit weight 2°C |
| 1 | 1 | R/W | bit weight 1°C |
| 0 | 1/2 | R/W | bit weight 1/2°C (0.5°C) |

All registers have 2's complement format. The offset range for each remote is +63.5°C/–64°C. The value programmed in this register is directly added to the actual reading of the ADC and the modified number is reported in the remote value registers.

CONFIGURATION REGISTERS

Main Configuration Register

| Register Name | Command Byte (Hex) | Read/Write | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 | POR Default (Hex) |
|---------------|--------------------|------------|----|------|----|----|----|----|------|------|-------------------|
| Configuration | 0x03 | R/W | – | STBY | – | – | – | – | R4QE | R3QE | 0x03 |

| Bit(s) | Bit Name | Read/Write | Description |
|--------|----------|------------|---|
| 7 | – | RO | Reserved will report "0" when read. |
| 6 | STBY | R/W | Software Standby 1 – standby (when in this mode one conversion sequence can be initiated by writing to the one-shot register) 0 – active/converting |
| 5–2 | – | RO | Reserved – will report "0" when read. |
| 1 | R4QE | R/W | Fault queue enable for Remote 4 1– Fault queue enabled 0– Fault queue disabled |
| 0 | R3QE | R/W | Fault queue enable for Remote 3 1– Fault queue enabled 0– Fault queue disabled |

Conversion Rate Register

| Register Name | Command Byte (Hex) | Read/Write | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 | POR Default (Hex) |
|-----------------|--------------------|------------|----|----|----|----|----|----|-----|-----|-------------------|
| Conversion Rate | 0x04 | R/W | – | – | – | – | – | – | CR1 | CR0 | 0x02 |

| Bit(s) | Bit Name | Read/Write | Description |
|--------|----------|------------|---|
| 7-2 | – | RO | Reserved – will report "0" when read. |
| 1-0 | CR[1:0] | R/W | Conversion rate control bits modify the time interval for conversion of the channels enabled. The channels enabled are converted sequentially then standby mode enabled for the remainder of the time interval. |
| | | | <div>CR[1:0]</div> <div>Conversion Rate</div> |
| | | | <div>00</div> <div>continuous (30 ms to 143 ms)</div> |
| | | | <div>01</div> <div>0.364 s</div> |
| | | | <div>10</div> <div>1s</div> |
| | | | <div>11</div> <div>2.5 s</div> |

Channel Conversion Enable

When a conversion is disabled for a particular channel it is skipped. The continuous conversion rate is effected all other conversion rates are not effected as extra standby time is inserted in order to compensate. See [Conversion Rate Register](#) description.

| Register Name | Command Byte (Hex) | Read/Write | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 | POR Default (Hex) |
|---------------------------|--------------------|------------|----|----|----|------|------|------|------|-----|-------------------|
| Channel Conversion Enable | 0x05 | R/W | – | – | – | R4CE | R3CE | R2CE | R1CE | LCE | 0x1F |

| Bit(s) | Bit Name | Read/Write | Description |
|--------|----------|------------|---|
| 7–5 | – | RO | Reserved – will report "0" when read. |
| 4 | R4CE | R/W | Remote 4 Temperature Conversion Enable 1– Remote 4 temp conversion enabled 0– Remote 4 temp conversion disabled |
| 3 | R3CE | R/W | Remote 3 Temperature Conversion Enable 1– Remote 3 temp conversion enabled 0– Remote 3 temp conversion disabled |
| 2 | R2CE | R/W | Remote 2 Temperature Conversion Enable 1– Remote 2 temp conversion enabled 0– Remote 2 temp conversion disabled |
| 1 | R1CE | R/W | Remote 1 Temperature Conversion Enable 1– Remote 1 temp conversion enabled 0– Remote 1 temp conversion disabled |
| 0 | LCE | R/W | Local Temperature Conversion Enable 1– Local temp conversion enabled 0– Local temp conversion disabled |

Filter Setting

| Register Name | Command Byte (Hex) | Read/Write | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 | POR Default (Hex) |
|----------------|--------------------|------------|----|----|----|----|------|------|------|------|-------------------|
| Filter Setting | 0x06 | R/W | – | – | – | – | R2F1 | R2F0 | R1F1 | R1F0 | 0x0F |

| Bit(s) | Bit Name | Read/Write | Description |
|--------|----------|------------|---|
| 7–4 | – | RO | Reserved – will report "0" when read. |
| 3–2 | R2F[1:0] | R/W | Remote Channel 2 Filter Enable Bits |
| | | | R2F[1:0] Digital Filter State |
| | | | 00 disable all digital filtering |
| | | | 01 enable basic filter |
| | | | 10 reserved (do not use) |
| | | | 11 enable enhanced filter |
| 1–0 | R1F[1:0] | R/W | Remote Channel 1 Filter Enable |
| | | | R1F[1:0] Filter State |
| | | | 00 disable all digital filtering |
| | | | 01 enable basic filter |
| | | | 10 reserved (do not use) |
| | | | 11 enable enhanced filter |

1-Shot

| Register Name | Command Byte (Hex) | Read/Write | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 | POR Default (Hex) |
|---------------|--------------------|------------|----|----|----|----|----|----|----|----|-------------------|
| 1-Shot | 0x0F | WO | – | – | – | – | – | – | – | – | – |

| Bit(s) | Bit Name | Read/Write | Description |
|--------|----------|------------|--|
| 7–0 | – | WO | Writing to this register activates one conversion for all the enabled channels if the chip is in standby mode (i.e. standby bit = 1). The actual data written does not matter and is not stored. |

STATUS REGISTERS**Common Status Register**

| Register Name | Command Byte (Hex) | Read/Write | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 | POR Default (Hex) |
|------------------------|--------------------|------------|------|----|----|----|------|------|------|------|-------------------|
| Common Status Register | 0x02 | RO | BUSY | NR | – | – | SR4F | SR3F | SR2F | SR1F | 0x00 |

| Bit(s) | Bit Name | Read/Write | Description |
|--------|----------|------------|--|
| 7 | BUSY | RO | Busy bit (device converting) |
| 6 | NR | RO | Not Ready bit (30 ms), indicates power up initialization sequence is in progress |
| 5–4 | – | RO | Reserved – will report "0" when read. |
| 3 | SR4F | RO | Status Register 4 Flag: 1 – indicates that Status Register 4 has at least one bit set 0 – indicates that all of Status Register 4 bits are cleared |
| 2 | SR3F | RO | Status Register 3 Flag: 1 – indicates that Status Register 3 has at least one bit set 0 – indicates that all of Status Register 3 bits are cleared |
| 1 | SR2F | RO | Status Register 2 Flag: 1 – indicates that Status Register 2 has at least one bit set 0 – indicates that all of Status Register 2 bits are cleared |
| 0 | SR1F | RO | Status Register 1 Flag: 1 – indicates that Status Register 1 has at least one bit set 0 – indicates that all of Status Register 1 bits are cleared |

Status 1 Register (Diode Fault)

Status fault bits for open or shorted diode (i.e. Short Fault: D+ shorted to Ground or D–; Open Fault: D+ shorted to V_{DD} , or floating). During fault conditions the temperature reading is 0 °C if unsigned value registers are read or –128.000 °C if signed value registers are read.

| Register Name | Command Byte (Hex) | Read/Write | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 | POR Default (Hex) |
|------------------------|--------------------|------------|------|------|------|------|------|------|------|------|-------------------|
| Status 1 (Diode Fault) | 0x07 | RO | R4DO | R4DS | R3DO | R3DS | R2DO | R2DS | R1DO | R1DS | – |

| Bit(s) | Bit Name | Read/Write | Description |
|--------|----------|------------|--|
| 7 | R4DO | RO | Remote 4 diode open fault status: 1 – indicates that remote 4 diode has an "open" fault 0 – indicates that remote 4 diode does not have an "open" fault |
| 6 | R4DS | RO | Remote 4 diode short fault status: 1 – indicates that remote 4 diode has a "short" fault 0 – indicates that remote 4 diode does not have a "short" fault |

| Bit(s) | Bit Name | Read/ Write | Description |
|--------|----------|----------------|--|
| 5 | R3DO | RO | Remote 3 diode open fault status: 1 – indicates that remote 3 diode has an "open" fault 0 – indicates that remote 3 diode does not have an "open" fault |
| 4 | R3DS | RO | Remote 3 diode short fault status: 1 – indicates that remote 3 diode has a "short" fault 0 – indicates that remote 3 diode does not have a "short" fault |
| 3 | R2DO | RO | Remote 2 diode open fault status: 1 – indicates that remote 2 diode has an "open" fault 0 – indicates that remote 2 diode does not have an "open" fault |
| 2 | R2DS | RO | Remote 2 diode short fault status: 1 – indicates that remote 2 diode has a "short" fault 0 – indicates that remote 2 diode does not have a "short" fault |
| 1 | R1DO | RO | Remote 1 diode open fault status: 1 – indicates that remote 1 diode has an "open" fault 0 – indicates that remote 1 diode does not have an "open" fault |
| 0 | R1DS | RO | Remote 1 diode short fault status: 1 – indicates that remote 1 diode has a "short" fault 0 – indicates that remote 1 diode does not have a "short" fault |

Status 2 ($\overline{\text{TCRIT1}}$)

Status bits for $\overline{\text{TCRIT1}}$. When one or more of these bits are set and if not masked the $\overline{\text{TCRIT1}}$ output will activate. $\overline{\text{TCRIT1}}$ will deactivate when all these bits are cleared.

| Register Name | Command Byte (Hex) | Read/ Write | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 | POR Default (Hex) |
|---|--------------------------|----------------|----|----|----|------|------|------|------|-----|-------------------------|
| Status 2 ($\overline{\text{TCRIT1}}$) | 0x08 | RO | – | – | – | R4T1 | R3T1 | R2T1 | R1T1 | LT1 | – |

| Bit(s) | Bit Name | Read/ Write | Description |
|--------|----------|----------------|--|
| 7–5 | - | RO | Reserved – will report "0" when read. |
| 4 | R4T1 | RO | Remote 4 Tcrit Status: 1 – indicates that remote 4 reading is greater than or equal to the value set in Remote 4 Tcrit Limit register 0 – indicates that that remote 4 reading is less than the value set in Remote 4 Tcrit Limit register minus the Common Hysteresis value |
| 3 | R3T1 | RO | Remote 3 Tcrit Status: 1 – indicates that remote 3 reading is greater than or equal to the value set in Remote 3 Tcrit Limit register 0 – indicates that that remote 3 reading is less than the value set in Remote 3 Tcrit Limit register minus the Common Hysteresis value |
| 2 | R2T1 | RO | Remote 2 Tcrit-1 Status: 1 – indicates that remote 2 reading is greater than or equal to the value set in Remote 2 Tcrit-1 Limit register 0 – indicates that that remote 2 reading is less than the value set in Remote 2 Tcrit-1 Limit register minus the Common Hysteresis value |
| 1 | R1T1 | RO | Remote 1 Tcrit-1 Status: 1 – indicates that remote 1 reading is greater than or equal to the value set in Remote 1 Tcrit-1 Limit register 0 – indicates that that remote 1 reading is less than the value set in Remote 1 Tcrit-1 Limit register minus the Common Hysteresis value |
| 0 | LT1 | RO | Local Tcrit Status: 1 – indicates that local reading is greater than or equal to the value set in Local Tcrit Limit register 0 – indicates that local reading is less than the value set in Local Tcrit Limit register minus the Common Hysteresis value |

Status 3 ($\overline{\text{TCRIT2}}$)

Status bits for $\overline{\text{TCRIT2}}$. When one or more of these bits are set and if not masked the $\overline{\text{TCRIT2}}$ output will activate. $\overline{\text{TCRIT2}}$ will deactivate when all these bits are cleared.

| Register Name | Command Byte (Hex) | Read/Write | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 | POR Default (Hex) |
|---|--------------------|------------|----|----|----|------|------|------|------|-----|-------------------|
| Status 3 ($\overline{\text{TCRIT2}}$) | 0x09 | RO | – | – | – | R4T2 | R3T2 | R2T2 | R1T2 | LT2 | – |

| Bit(s) | Bit Name | Read/Write | Description |
|--------|----------|------------|--|
| 7–5 | – | RO | Reserved – will report "0" when read. |
| 4 | R4T2 | RO | Remote 4 Tcrit Status: 1 – indicates that remote 4 reading is greater than or equal to the value set in Remote 4 Tcrit Limit register 0 – indicates that that remote 4 reading is less than the value set in Remote 4 Tcrit Limit register minus the Common Hysteresis value |
| 3 | R3T2 | RO | Remote 3 Tcrit Status: 1 – indicates that remote 3 reading is greater than or equal to the value set in Remote 3 Tcrit Limit register 0 – indicates that that remote 3 reading is less than the value set in Remote 3 Tcrit Limit register minus the Common Hysteresis value |
| 2 | R2T2 | RO | Remote 2 Tcrit-2 Status: 1 – indicates that remote 2 reading is greater than or equal to the value set in Remote 2 Tcrit-2 Limit register 0 – indicates that that remote 2 reading is less than the value set in Remote 2 Tcrit-2 Limit register minus the Common Hysteresis value |
| 1 | R1T2 | RO | Remote 1 Tcrit-2 Status: 1 – indicates that remote 1 reading is greater than or equal to the value set in Remote 1 Tcrit-2 Limit register 0 – indicates that that remote 1 reading is less than the value set in Remote 1 Tcrit-2 Limit register minus the Common Hysteresis value |
| 0 | LT2 | RO | Local Tcrit Status: 1 – indicates that local reading is greater than or equal to the value set in Local Tcrit Limit register 0 – indicates that local reading is less than the value set in Local Tcrit Limit register minus the Common Hysteresis value |

Status 4 ($\overline{\text{TCRIT3}}$)

Status bits for $\overline{\text{TCRIT3}}$. When one or more of these bits are set and if not masked the $\overline{\text{TCRIT3}}$ output will activate. $\overline{\text{TCRIT3}}$ will deactivate when all these bits are cleared.

| Register Name | Command Byte (Hex) | Read/Write | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 | POR Default (Hex) |
|---|--------------------|------------|----|----|----|------|------|------|------|-----|-------------------|
| Status 4 ($\overline{\text{TCRIT3}}$) | 0x0A | RO | – | – | – | R4T3 | R3T3 | R2T3 | R1T3 | LT3 | – |

| Bit(s) | Bit Name | Read/Write | Description |
|--------|----------|------------|--|
| 7–5 | – | RO | Reserved – will report "0" when read. |
| 4 | R4T3 | RO | Remote 4 Tcrit Status: 1 – indicates that remote 4 reading is greater than or equal to the value set in Remote 4 Tcrit Limit register 0 – indicates that that remote 4 reading is less than the value set in Remote 4 Tcrit Limit register minus the Common Hysteresis value |
| 3 | R3T3 | RO | Remote 3 Tcrit Status: 1 – indicates that remote 3 reading is greater than or equal to the value set in Remote 3 Tcrit Limit register 0 – indicates that that remote 3 reading is less than the value set in Remote 3 Tcrit Limit register minus the Common Hysteresis value |

| Bit(s) | Bit Name | Read/ Write | Description |
|--------|----------|----------------|--|
| 2 | R2T3 | RO | Remote 2 Tcrit-2 Status: 1 – indicates that remote 2 reading is greater than or equal to the value set in Remote 2 Tcrit-2 Limit register 0 – indicates that that remote 2 reading is less than the value set in Remote 2 Tcrit-2 Limit register minus the Common Hysteresis value |
| 1 | R1T3 | RO | Remote 1 Tcrit-2 Status: 1 – indicates that remote 1 reading is greater than or equal to the value set in Remote 1 Tcrit-2 Limit register 0 – indicates that that remote 1 reading is less than the value set in Remote 1 Tcrit-2 Limit register minus the Common Hysteresis value |
| 0 | LT3 | RO | Local Tcrit Status: 1 – indicates that local reading is greater than or equal to the value set in Local Tcrit Limit register 0 – indicates that local reading is less than the value set in Local Tcrit Limit register minus the Common Hysteresis value |

MASK REGISTERS

TCRIT1 Mask Register

The mask bits in this register allow control over which error events propagate to the $\overline{\text{TCRIT1}}$ pin.

| Register Name | Command Byte (Hex) | Read/ Write | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 | POR Default (Hex) |
|---------------------------------|--------------------------|----------------|----|----|----|------|------|-----------|-----------|-----|-------------------------|
| $\overline{\text{TCRIT1}}$ Mask | 0x0C | R/W | – | – | – | R4TM | R3TM | R2T1 M | R1T1 M | LTM | 0x19 |

| Bit(s) | Bit Name | Read/ Write | Description |
|--------|----------|----------------|--|
| 7-5 | – | RO | Reserved – will report "0" when read. |
| 4 | R4TM | R/W | Remote 4 Tcrit Mask: 1 – prevents the remote 4 temperature error event from propagating to the $\overline{\text{TCRIT1}}$ pin 0 – allows the remote 4 temperature error event to propagate to the $\overline{\text{TCRIT1}}$ pin |
| 3 | R3TM | R/W | Remote 3 Tcrit Mask: 1 – prevents the remote 3 temperature error event from propagating to the $\overline{\text{TCRIT1}}$ pin 0 – allows the remote 3 temperature error event to propagate to the $\overline{\text{TCRIT1}}$ pin |
| 2 | R2T1M | R/W | Remote 2 Tcrit-1 Mask: 1 – prevents the remote 2 temperature error event from propagating to the $\overline{\text{TCRIT1}}$ pin 0 – allows the remote 2 temperature error event to propagate to the $\overline{\text{TCRIT1}}$ pin |
| 1 | R1T1M | R/W | Remote 1 Tcrit-1 Mask: 1 – prevents the remote 1 temperature error event from propagating to the $\overline{\text{TCRIT1}}$ pin 0 – allows the remote 1 temperature error event to propagate to the $\overline{\text{TCRIT1}}$ pin |
| 0 | LTM | R/W | Local Tcrit Mask: 1 – prevents the local temperature error event from propagating to the $\overline{\text{TCRIT1}}$ pin 0 – allows the local temperature error event to propagate to the $\overline{\text{TCRIT1}}$ pin |

TCRIT2 Mask Registers

| Register Name | Command Byte (Hex) | Read/ Write | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 | POR Default (Hex) |
|---------------------------------|--------------------------|----------------|----|----|----|------|------|-----------|-----------|-----|-------------------------|
| $\overline{\text{TCRIT2}}$ Mask | 0x0D | R/W | – | – | – | R4TM | R3TM | R2T2 M | R1T2 M | LTM | 0x00 |

| Bit(s) | Bit Name | Read/ Write | Description |
|--------|----------|----------------|--|
| 7-5 | – | RO | Reserved – will report "0" when read. |
| 4 | R4TM | R/W | Remote 4 Tcrit Mask: 1 – prevents the remote 4 temperature error event from propagating to the $\overline{\text{TCRIT2}}$ pin 0 – allows the remote 4 temperature error event to propagate to the $\overline{\text{TCRIT2}}$ pin |

| Bit(s) | Bit Name | Read/ Write | Description |
|--------|----------|----------------|--|
| 3 | R3TM | R/W | Remote 3 Tcrit Mask: 1 – prevents the remote 3 temperature error event from propagating to the $\overline{\text{TCRIT2}}$ pin 0 – allows the remote 3 temperature error event to propagate to the $\overline{\text{TCRIT2}}$ pin |
| 2 | R2T2M | R/W | Remote 2 Tcrit-2 Mask: 1 – prevents the remote 2 temperature error event from propagating to the $\overline{\text{TCRIT2}}$ pin 0 – allows the remote 2 temperature error event to propagate to the $\overline{\text{TCRIT2}}$ pin |
| 1 | R1T2M | R/W | Remote 1 Tcrit-2 Mask: 1 – prevents the remote 1 temperature error event from propagating to the $\overline{\text{TCRIT2}}$ pin 0 – allows the remote 1 temperature error event to propagate to the $\overline{\text{TCRIT2}}$ pin |
| 0 | LTM | R/W | Local Tcrit Mask: 1 – prevents the local temperature error event from propagating to the $\overline{\text{TCRIT2}}$ pin 0 – allows the local temperature error event to propagate to the $\overline{\text{TCRIT2}}$ pin |

$\overline{\text{TCRIT3}}$ Mask Register

The mask bits in this register allow control over which error events propagate to the $\overline{\text{TCRIT3}}$ pin.

| Register Name | Command Byte (Hex) | Read/ Write | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 | POR Default (Hex) |
|---------------------------------|--------------------------|----------------|----|----|----|------|------|-----------|-----------|-----|-------------------------|
| $\overline{\text{TCRIT3}}$ Mask | 0x0E | R/W | – | – | – | R4TM | R3TM | R2T2 M | R1T2 M | LTM | 0x07 |

| Bit(s) | Bit Name | Read/ Write | Description |
|--------|----------|----------------|--|
| 7-5 | – | RO | Reserved – will report "0" when read. |
| 4 | R4TM | R/W | Remote 4 Tcrit Mask: 1 – prevents the remote 4 temperature error event from propagating to the $\overline{\text{TCRIT3}}$ pin 0 – allows the remote 4 temperature error event to propagate to the $\overline{\text{TCRIT3}}$ pin |
| 3 | R3TM | R/W | Remote 3 Tcrit Mask: 1 – prevents the remote 3 temperature error event from propagating to the $\overline{\text{TCRIT3}}$ pin 0 – allows the remote 3 temperature error event to propagate to the $\overline{\text{TCRIT3}}$ pin |
| 2 | R2T2M | R/W | Remote 2 Tcrit-2 Mask: 1 – prevents the remote 2 temperature error event from propagating to the $\overline{\text{TCRIT3}}$ pin 0 – allows the remote 2 temperature error event to propagate to the $\overline{\text{TCRIT3}}$ pin |
| 1 | R1T2M | R/W | Remote 1 Tcrit-2 Mask: 1 – prevents the remote 1 temperature error event from propagating to the $\overline{\text{TCRIT3}}$ pin 0 – allows the remote 1 temperature error event to propagate to the $\overline{\text{TCRIT3}}$ pin |
| 0 | LTM | R/W | Local Tcrit Mask: 1 – prevents the local temperature error event from propagating to the $\overline{\text{TCRIT3}}$ pin 0 – allows the local temperature error event to propagate to the $\overline{\text{TCRIT3}}$ pin |

LIMIT REGISTERS

Local Limit Register

The Local Limit register range is 0°C to 127°C. The value programmed in this register is used to determine a local temperature error event.

| Register Name | Command Byte (Hex) | Read/ Write | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 | POR Default (Hex) |
|-------------------|--------------------------|----------------|----|----|----|----|----|----|----|----|-------------------------|
| Local Tcrit Limit | 0x40 | R/W | 0 | 64 | 32 | 16 | 8 | 4 | 2 | 1 | 0x55 |

| Bit(s) | Bit Name | Read/ Write | Description |
|--------|----------|----------------|---------------------------------------|
| 7 | 0 | RO | Read only bit will always report "0". |
| 6 | 64 | R/W | bit weight 64°C |
| 5 | 32 | R/W | bit weight 32°C |

| Bit(s) | Bit Name | Read/ Write | Description |
|--------|----------|----------------|-----------------|
| 4 | 16 | R/W | bit weight 16°C |
| 3 | 8 | R/W | bit weight 8°C |
| 2 | 4 | R/W | bit weight 4°C |
| 1 | 2 | R/W | bit weight 2°C |
| 0 | 1 | R/W | bit weight 1°C |

Remote Limit Registers

The range for these registers is 0°C to 255°C.

| Register Name | Command Byte (Hex) | Read/ Write | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 | POR Default (Hex) |
|--|--------------------------|----------------|-----|----|----|----|----|----|----|----|-------------------------|
| Remote 1 Tcrit-1 Limit (used by $\overline{\text{TCRIT1}}$ error events) | 0x41 | R/W | 128 | 64 | 32 | 16 | 8 | 4 | 2 | 1 | 0x6E |
| Remote 2 Tcrit-1 Limit (used by $\overline{\text{TCRIT1}}$ error events) | 0x42 | R/W | 128 | 64 | 32 | 16 | 8 | 4 | 2 | 1 | 0x6E |
| Remote 3 Tcrit Limit (used by $\overline{\text{TCRIT1}}$, $\overline{\text{TCRIT2}}$ and $\overline{\text{TCRIT3}}$ error events) | 0x43 | R/W | 128 | 64 | 32 | 16 | 8 | 4 | 2 | 1 | 0x55 |
| Remote 4 Tcrit Limit (used by $\overline{\text{TCRIT1}}$, $\overline{\text{TCRIT2}}$ and $\overline{\text{TCRIT3}}$ error events) | 0x44 | R/W | 128 | 64 | 32 | 16 | 8 | 4 | 2 | 1 | 0x55 |
| Remote 1 Tcrit-2 and Tcrit3 Limit (used by $\overline{\text{TCRIT2}}$ and $\overline{\text{TCRIT3}}$ error events) | 0x49 | R/W | 128 | 64 | 32 | 16 | 8 | 4 | 2 | 1 | 0x55 |
| Remote 2 Tcrit-2 and Tcrit3 Limit (used by $\overline{\text{TCRIT2}}$ and $\overline{\text{TCRIT3}}$ error events) | 0x4A | R/W | 128 | 64 | 32 | 16 | 8 | 4 | 2 | 1 | 0x55 |

| Bit(s) | Bit Name | Read/ Write | Description |
|--------|----------|----------------|------------------|
| 7 | 128 | R/W | bit weight 128°C |
| 6 | 64 | R/W | bit weight 64°C |
| 5 | 32 | R/W | bit weight 32°C |
| 4 | 16 | R/W | bit weight 16°C |
| 3 | 8 | R/W | bit weight 8°C |
| 2 | 4 | R/W | bit weight 4°C |
| 1 | 2 | R/W | bit weight 2°C |
| 0 | 1 | R/W | bit weight 1°C |

Limit assignments for each $\overline{\text{TCRIT}}$ output pin:

| Output Pin | Remote 4 | Remote 3 | Remote 2 | Remote 1 | Local |
|----------------------------|----------------------|----------------------|------------------------|------------------------|-------------------|
| $\overline{\text{TCRIT1}}$ | Remote 4 Tcrit Limit | Remote 3 Tcrit Limit | Remote 2 Tcrit-1 Limit | Remote 1 Tcrit-1 Limit | Local Tcrit Limit |
| $\overline{\text{TCRIT2}}$ | Remote 4 Tcrit Limit | Remote 3 Tcrit Limit | Remote 2 Tcrit-2 Limit | Remote 1 Tcrit-2 Limit | Local Tcrit Limit |
| $\overline{\text{TCRIT3}}$ | Remote 4 Tcrit Limit | Remote 3 Tcrit Limit | Remote 2 Tcrit-2 Limit | Remote 1 Tcrit-2 Limit | Local Tcrit Limit |

Common Tcrit Hysteresis Register

The hysteresis register range is 0°C to 32°C. The value programmed in this register is used to modify all the limit values for decreasing temperature.

| Register Name | Command Byte (Hex) | Read/Write | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 | POR Default (Hex) |
|-------------------------|--------------------|------------|----|----|----|----|----|----|----|----|-------------------|
| Common Tcrit Hysteresis | 0x5A | R/W | 0 | 0 | 0 | 16 | 8 | 4 | 2 | 1 | 0x0A |

| Bit(s) | Bit Name | Read/Write | Description |
|--------|----------|------------|---------------------------------------|
| 7 | 0 | RO | Read only bit will always report "0". |
| 6 | 0 | RO | Read only bit will always report "0". |
| 5 | 0 | RO | Read only bit will always report "0". |
| 4 | 16 | R/W | bit weight 16°C |
| 3 | 8 | R/W | bit weight 8°C |
| 2 | 4 | R/W | bit weight 4°C |
| 1 | 2 | R/W | bit weight 2°C |
| 0 | 1 | R/W | bit weight 1°C |

IDENTIFICATION REGISTERS

| Register Name | Command Byte (Hex) | Read/Write | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 | POR Default (Hex) |
|-----------------|--------------------|------------|----|----|----|----|----|----|----|----|-------------------|
| Manufacturer ID | 0xFE | RO | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 1 | 0x01 |
| Revision ID | 0xFF | RO | 0 | 1 | 1 | 1 | 1 | 0 | 1 | 1 | 0x7B |

Applications Hints

The LM95214 can be applied easily in the same way as other integrated-circuit temperature sensors, and its remote diode sensing capability allows it to be used in new ways as well. It can be soldered to a printed circuit board, and because the path of best thermal conductivity is between the die and the pins, its temperature will effectively be that of the printed circuit board lands and traces soldered to the LM95214's pins. This presumes that the ambient air temperature is almost the same as the surface temperature of the printed circuit board; if the air temperature is much higher or lower than the surface temperature, the actual temperature of the LM95214 die will be at an intermediate temperature between the surface and air temperatures. Again, the primary thermal conduction path is through the leads, so the circuit board temperature will contribute to the die temperature much more strongly than will the air temperature.

To measure temperature external to the LM95214's die, incorporates remote diode sensing technology. This diode can be located on the die of a target IC, allowing measurement of the IC's temperature, independent of the LM95214's temperature. A discrete diode can also be used to sense the temperature of external objects or ambient air. Remember that a discrete diode's temperature will be affected, and often dominated, by the temperature of its leads. Most silicon diodes do not lend themselves well to this application. It is recommended that an MMBT3904 transistor base emitter junction be used with the collector tied to the base.

The LM95214 can measure a diode-connected transistor such as the MMBT3904 or the thermal diode found in an AMD processor. The LM95214 has been optimized to measure the MMBT3904 remote thermal diode the offset register can be used to calibrate for other thermal diodes easily. The LM95214 does not include TruTherm™ technology that allows sensing of sub-micron geometry process thermal diodes. For this application the LM95234 would be better suited.

The LM95234 has been specifically optimized to measure the remote thermal diode integrated in a typical Intel processor on 65 nm or 90 nm process or an MMBT3904 transistor. Using the Remote Diode Model Select register found in the LM95234 any of the four remote inputs can be optimized for a typical Intel processor on 65 nm or 90 nm process or an MMBT3904.

DIODE NON-IDEALITY

Diode Non-Ideality Factor Effect on Accuracy

When a transistor is connected as a diode, the following relationship holds for variables V_{BE} , T and I_F :

$$I_F = I_S \times \left[e^{\left(\frac{V_{BE}}{\eta \times V_t} \right)} - 1 \right]$$

where

- $V_t = \frac{kT}{q}$
- $q = 1.6 \times 10^{-19}$ Coulombs (the electron charge)
- T = Absolute Temperature in Kelvin
- $k = 1.38 \times 10^{-23}$ joules/K (Boltzmann's constant)
- η is the non-ideality factor of the process the diode is manufactured on
- I_S = Saturation Current and is process dependent
- I_F = Forward Current through the base-emitter junction
- V_{BE} = Base-Emitter Voltage drop

(1)

In the active region, the -1 term is negligible and may be eliminated, yielding the following equation

$$I_F = I_S \times \left[e^{\left(\frac{V_{BE}}{\eta \times V_t} \right)} \right]$$

(2)

In [Equation 2](#), η and I_S are dependant upon the process that was used in the fabrication of the particular diode. By forcing two currents with a very controlled ratio (I_{F2} / I_{F1}) and measuring the resulting voltage difference, it is possible to eliminate the I_S term. Solving for the forward voltage difference yields the relationship:

$$\Delta V_{BE} = \eta \times \left(\frac{kT}{q} \right) \times \ln \left(\frac{I_{F2}}{I_{F1}} \right)$$

(3)

Solving [Equation 3](#) for temperature yields:

$$T = \frac{q \times \Delta V_{BE}}{\eta \times k \times \ln \left(\frac{I_{F2}}{I_{F1}} \right)}$$

(4)

[Equation 4](#) holds true when a diode connected transistor such as the MMBT3904 is used. When this “diode” equation is applied to an integrated diode such as a processor transistor with its collector tied to GND as shown in [Figure 21](#) it will yield a wide non-ideality spread. This wide non-ideality spread is not due to true process variation but due to the fact that [Equation 4](#) is an approximation.

Texas Instruments invented TruTherm beta cancellation technology that uses the transistor equation, [Equation 5](#), which is a more accurate representation of the topology of the thermal diode found in some sub-micron FPGAs or processors.

$$T = \frac{q \times \Delta V_{BE}}{\eta \times k \times \ln \left(\frac{I_{C2}}{I_{C1}} \right)}$$

(5)

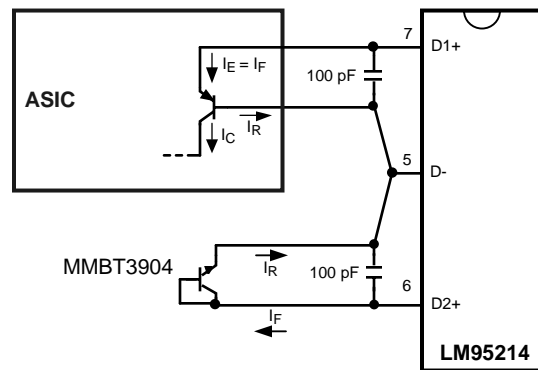


Figure 21. Thermal Diode Current Paths

TruTherm technology can be found in the LM95234 four channel remote diode sensor that is pin and register compatible with the LM95214. The LM95214 does not support this technology.

Calculating Total System Accuracy

The voltage seen by the LM95214 also includes the $I_F R_S$ voltage drop of the series resistance. The non-ideality factor, η , is the only other parameter not accounted for and depends on the diode that is used for measurement. Since ΔV_{BE} is proportional to both η and T , the variations in η cannot be distinguished from variations in temperature. Since the non-ideality factor is not controlled by the temperature sensor, it will directly add to the inaccuracy of the sensor. For the Intel processor on 65 nm process, Intel specifies a +4.06%/–0.897% variation in η from part to part when the processor diode is measured by a circuit that assumes diode equation, Equation 4, as true. As an example, assume a temperature sensor has an accuracy specification of $\pm 1.0^\circ\text{C}$ at a temperature of 80°C (353 Kelvin) and the processor diode has a non-ideality variation of +1.19%/–0.27%. The resulting system accuracy of the processor temperature being sensed will be:

$$T_{ACC} = +1.0^\circ\text{C} + (+4.06\% \text{ of } 353 \text{ K}) = +15.3^\circ\text{C}$$

and

$$T_{ACC} = -1.0^\circ\text{C} + (-0.89\% \text{ of } 353 \text{ K}) = -4.1^\circ\text{C}$$

The next error term to be discussed is that due to the series resistance of the thermal diode and printed circuit board traces. The thermal diode series resistance is specified on most processor data sheets. For the MMBT3904 transistor, this is specified at 0Ω typical. The LM95214 accommodates the typical series resistance of a circuit with the offset register compensation. The error that is not accounted for is the spread of the thermal diodes series resistance. If a circuit has a series resistance spread that is 2.79Ω to 6.24Ω or $4.515\Omega \pm 1.73\Omega$, the 4.515Ω can be cancelled out with the offset register setting. The $\pm 1.73\Omega$ spread cannot be cancelled out. The equation to calculate the temperature error due to series resistance (T_{ER}) for the LM95214 is simply:

$$T_{ER} = \left(0.62 \frac{^\circ\text{C}}{\Omega} \right) \times R_{PCB} \quad (6)$$

Solving Equation 6 for R_{PCB} equal to $\pm 1.73\Omega$ results in the additional error due to the spread in the series resistance of $\pm 1.07^\circ\text{C}$. The bulk of the error caused by the 4.515 ohms will cause a positive offset in the temperature reading of 2.79°C which can be cancelled out by setting the offset register to -2.75°C . The spread in error cannot be canceled out, as it would require measuring each individual thermal diode device. This is quite difficult and impractical in a large volume production environment.

Equation 6 can also be used to calculate the additional error caused by series resistance on the printed circuit board. Since the variation of the PCB series resistance is minimal, the bulk of the error term is always positive and can simply be cancelled out by subtracting it from the output readings of the LM95214.

| Processor Family | Diode Equation η_D , non-ideality | | | Series R, Ω |
|---|--|---------|---------|--------------------|
| | min | typ | max | |
| Pentium™ III CPUID 67h | 1 | 1.0065 | 1.0125 | |
| Pentium III CPUID 68h/PGA370Socket/ Celeron | 1.0057 | 1.008 | 1.0125 | |
| Pentium 4, 423 pin | 0.9933 | 1.0045 | 1.0368 | |
| Pentium 4, 478 pin | 0.9933 | 1.0045 | 1.0368 | |
| Pentium 4 on 0.13 micron process, 2 - 3.06 GHz | 1.0011 | 1.0021 | 1.0030 | 3.64 |
| Pentium 4 on 90 nm process | 1.0083 | 1.011 | 1.023 | 3.33 |
| Intel Processor on 65 nm process | 1.000 | 1.009 | 1.050 | 4.52 |
| Pentium M (Centrino) | 1.00151 | 1.00220 | 1.00289 | 3.06 |
| MMBT3904 | | 1.003 | | |
| AMD Athlon MP model 6 | 1.002 | 1.008 | 1.016 | |
| AMD Athlon 64 | 1.008 | 1.008 | 1.096 | |
| AMD Opteron | 1.008 | 1.008 | 1.096 | |
| AMD Sempron | | 1.00261 | | 0.93 |

Compensating for Different Non-Ideality

In order to compensate for the errors introduced by non-ideality, the temperature sensor is calibrated for a particular processor. Texas Instruments temperature sensors are always calibrated to the typical non-ideality and series resistance of a given transistor type. The LM95214 is calibrated for the non-ideality factor and series resistance values of the MMBT3904 transistor without the requirement for additional trims. When a temperature sensor calibrated for a particular thermal diode type is used with a different thermal diode type, additional errors are introduced.

Temperature errors associated with non-ideality of different processor types may be reduced in a specific temperature range of concern through use of software calibration. Typical Non-ideality specification differences cause a gain variation of the transfer function, therefore the center of the temperature range of interest should be the target temperature for calibration purposes. The following equation can be used to calculate the temperature correction factor (T_{CF}) required to compensate for a target non-ideality differing from that supported by the LM95214.

$$T_{CF} = \left(\frac{\eta_S - \eta_{PROCESSOR}}{\eta_S} \right) \times (T_{CR} + 273K)$$

where

- η_S = LM95214 non-ideality for accuracy specification
- $\eta_{PROCESSOR}$ = Processor thermal diode typical non-ideality
- T_{CR} = center of the temperature range of interest in °C

(7)

where

The correction factor should be directly added to the temperature reading produced by the LM95214. For example when using the LM95214, with the 3904 mode selected, to measure a AMD Athlon processor, with a typical non-ideality of 1.008, for a temperature range of 60 °C to 100 °C the correction factor would calculate to:

$$T_{CF} = \left(\frac{1.003 - 1.008}{1.003} \right) \cdot (80 + 273) = -1.75^\circ\text{C}$$

(8)

Therefore, 1.75°C should be subtracted from the temperature readings of the LM95214 to compensate for the differing typical non-ideality target.

PCB LAYOUT FOR MINIMIZING NOISE

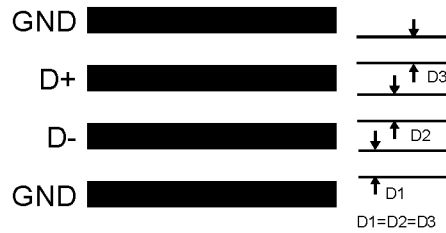


Figure 22. Ideal Diode Trace Layout

In a noisy environment, such as a processor mother board, layout considerations are very critical. Noise induced on traces running between the remote temperature diode sensor and the LM95214 can cause temperature conversion errors. Keep in mind that the signal level the LM95214 is trying to measure is in microvolts. The following guidelines should be followed:

1. V_{DD} should be bypassed with a 0.1 μF capacitor in parallel with 100 pF. The 100 pF capacitor should be placed as close as possible to the power supply pin. A bulk capacitance of approximately 10 μF needs to be in the near vicinity of the LM95214.
2. A 100 pF diode bypass capacitor is recommended to filter high frequency noise but may not be necessary. Make sure the traces to the 100 pF capacitor are matched. Place the filter capacitors close to the LM95214 pins.
3. Ideally, the LM95214 should be placed within 10 cm of the Processor diode pins with the traces being as straight, short and identical as possible. Trace resistance of 1 Ω can cause as much as 0.62°C of error. This error can be compensated by using simple software offset compensation.
4. Diode traces should be surrounded by a GND guard ring to either side, above and below if possible. This GND guard should not be between the D+ and D- lines. In the event that noise does couple to the diode lines it would be ideal if it is coupled common mode. That is equally to the D+ and D- lines.
5. Avoid routing diode traces in close proximity to power supply switching or filtering inductors.
6. Avoid running diode traces close to or parallel to high speed digital and bus lines. Diode traces should be kept at least 2 cm apart from the high speed digital traces.
7. If it is necessary to cross high speed digital traces, the diode traces and the high speed digital traces should cross at a 90 degree angle.
8. The ideal place to connect the LM95214's GND pin is as close as possible to the Processors GND associated with the sense diode.
9. Leakage current between D+ and GND and between D+ and D- should be kept to a minimum. Thirteen nano-amperes of leakage can cause as much as 0.2°C of error in the diode temperature reading. Keeping the printed circuit board as clean as possible will minimize leakage current.

Noise coupling into the digital lines greater than 400 mVp-p (typical hysteresis) and undershoot less than 500 mV below GND, may prevent successful SMBus communication with the LM95214. SMBus no acknowledge is the most common symptom, causing unnecessary traffic on the bus. Although the SMBus maximum frequency of communication is rather low (100 kHz max), care still needs to be taken to ensure proper termination within a system with multiple parts on the bus and long printed circuit board traces. An RC lowpass filter with a 3 dB corner frequency of about 40 MHz is included on the LM95214's SMBCLK input. Additional resistance can be added in series with the SMBDAT and SMBCLK lines to further help filter noise and ringing. Minimize noise coupling by keeping digital traces out of switching power supply areas as well as ensuring that digital lines containing high speed data communications cross at right angles to the SMBDAT and SMBCLK lines.

REVISION HISTORY

| Changes from Original (March 2013) to Revision A | Page |
|--|--------------------|
| • Changed layout of National Data Sheet to TI format | 38 |

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|-------------------|---------------|--------------|--------------------|------|----------------|----------------------------|------------------|----------------------|--------------|-------------------------|-------------------------|
| LM95214CISD/NOPB | ACTIVE | WSO | NHL | 14 | 1000 | Green (RoHS & no Sb/Br) | CU SN | Level-1-260C-UNLIM | -40 to 140 | 95214CI | Samples |
| LM95214CISDX/NOPB | ACTIVE | WSO | NHL | 14 | 4500 | Green (RoHS & no Sb/Br) | CU SN | Level-1-260C-UNLIM | -40 to 140 | 95214CI | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

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TAPE AND REEL INFORMATION


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|-------------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| LM95214CISD/NOPB | WSO | NHL | 14 | 1000 | 178.0 | 12.4 | 4.3 | 4.3 | 1.3 | 8.0 | 12.0 | Q1 |
| LM95214CISDX/NOPB | WSO | NHL | 14 | 4500 | 330.0 | 12.4 | 4.3 | 4.3 | 1.3 | 8.0 | 12.0 | Q1 |

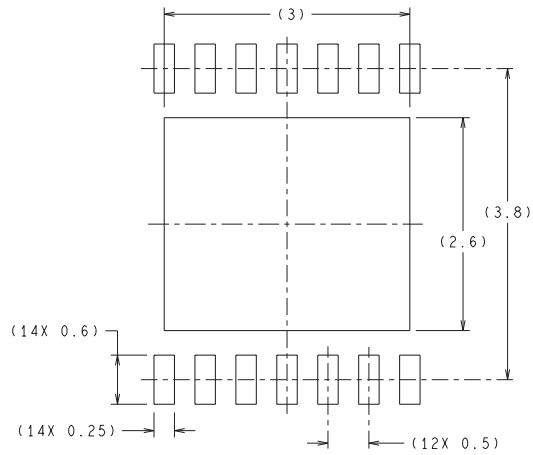
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

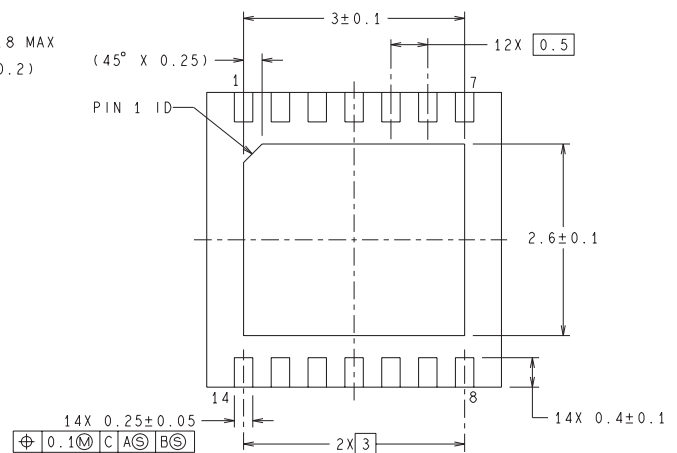
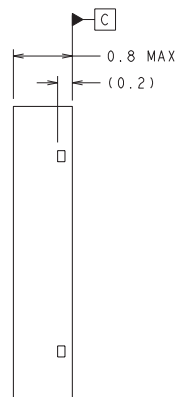
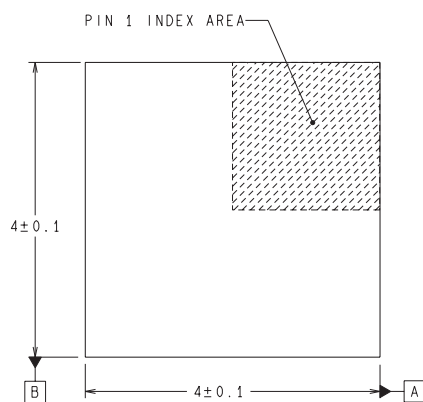
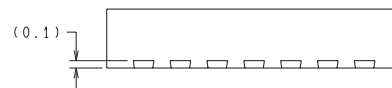
| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|-------------------|--------------|-----------------|------|------|-------------|------------|-------------|
| LM95214CISD/NOPB | WSO | NHL | 14 | 1000 | 210.0 | 185.0 | 35.0 |
| LM95214CISDX/NOPB | WSO | NHL | 14 | 4500 | 367.0 | 367.0 | 35.0 |

NHL0014B



RECOMMENDED LAND PATTERN

DIMENSIONS ARE IN MILLIMETERS
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SDA14B (Rev A)

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